

Future Outlook to Terahertz Communications

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Outline

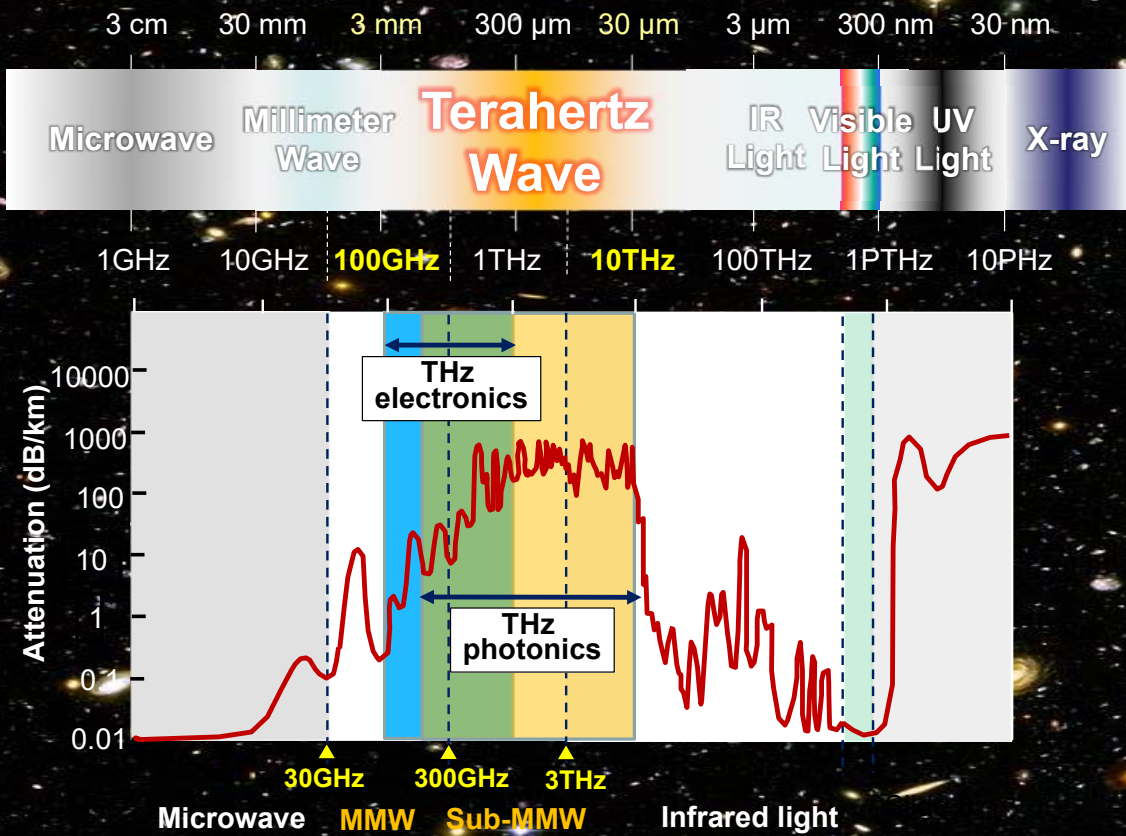
Review current status of THz communications research and discuss the future direction

1. State of the art

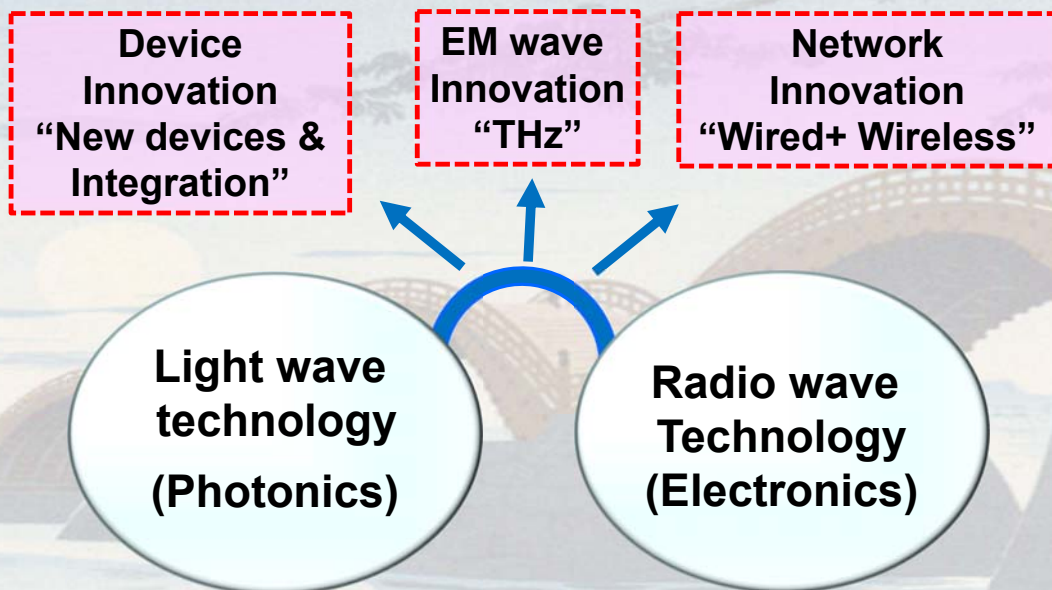
- ***selection of frequencies/bands***
- ***transceiver and system technologies: photonics vs. electronics***

2. Future directions

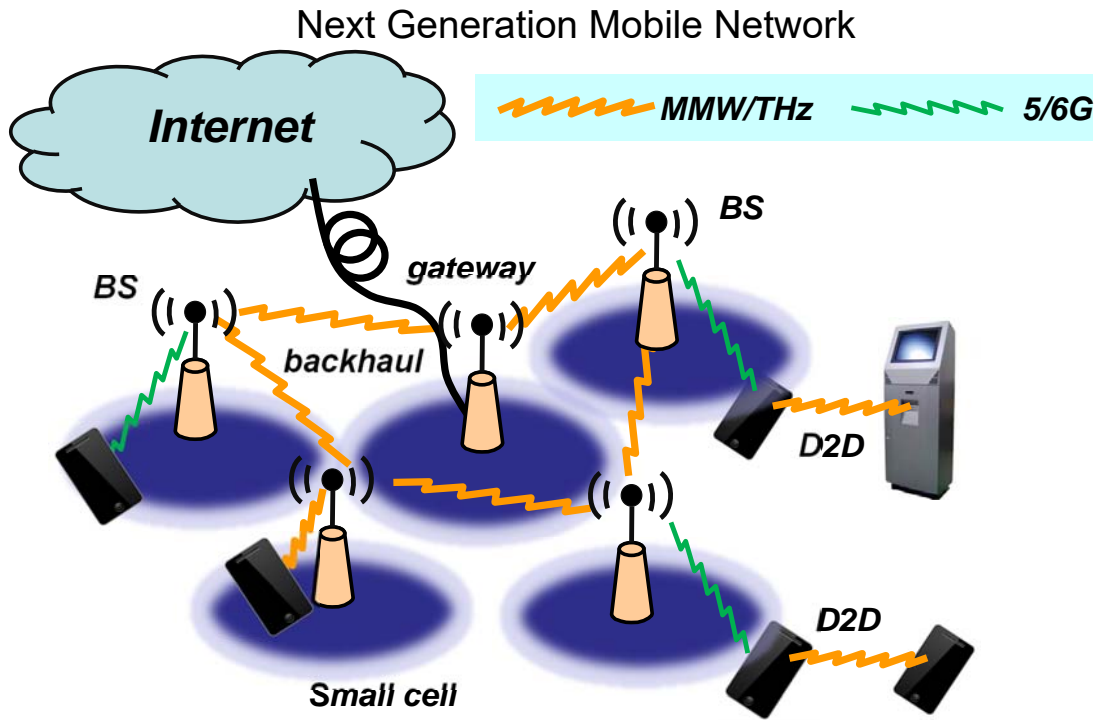
- ***device technologies***
- ***system integration technologies***
expectation for TERAway



Bridging Light and Radio Waves



Network Innovation: Wireless Backhaul



International Consensus below 275 GHz

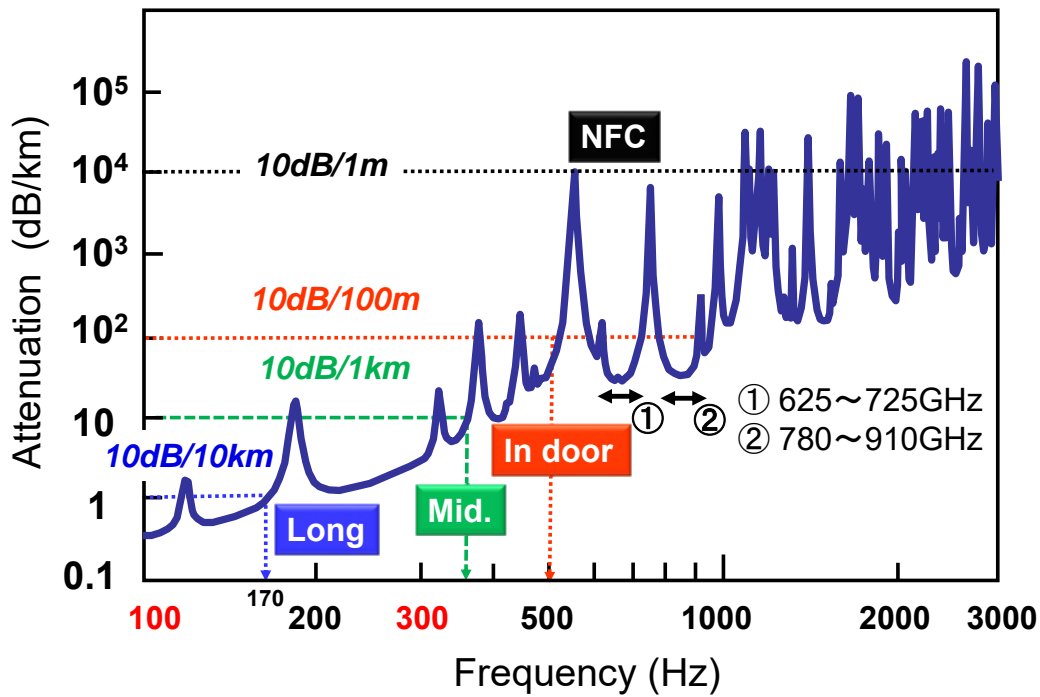
Prohibited Bands

Above 50GHz
52.4~50.4 GHz
52.6~54.25
86~92
100~102
109.5~111.8
114.25~116
148.5~151.5
164~167
182~185
190~191.8
200~209
226~231.5
250~252

Allocated for Fixed and Mobile

Frequency(GHz)	BW
102~109.5	7.5
111.8~114.25	2.45
122.25~123	0.75
130~134	4.0
141~148.5	7.5
151.5~164	12.5
167~174.8	7.8
191.8~200	8.2
209~226	17.0
232~235	3.0
238~241	3.0
252~275	23.0

Link Distance Determined by Attenuation

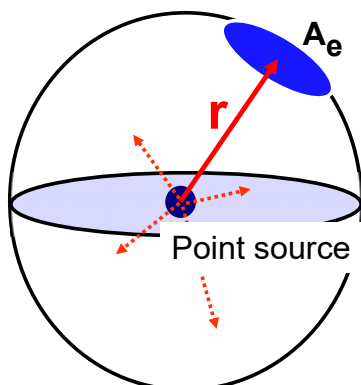


Another Loss: FSPL

Free-Space Propagation Loss (FSPL)

$$\Gamma = \left(\frac{4\pi r}{\lambda} \right)^2 = \left(\frac{4\pi f r}{c} \right)^2$$

Loss is proportional to square of frequency

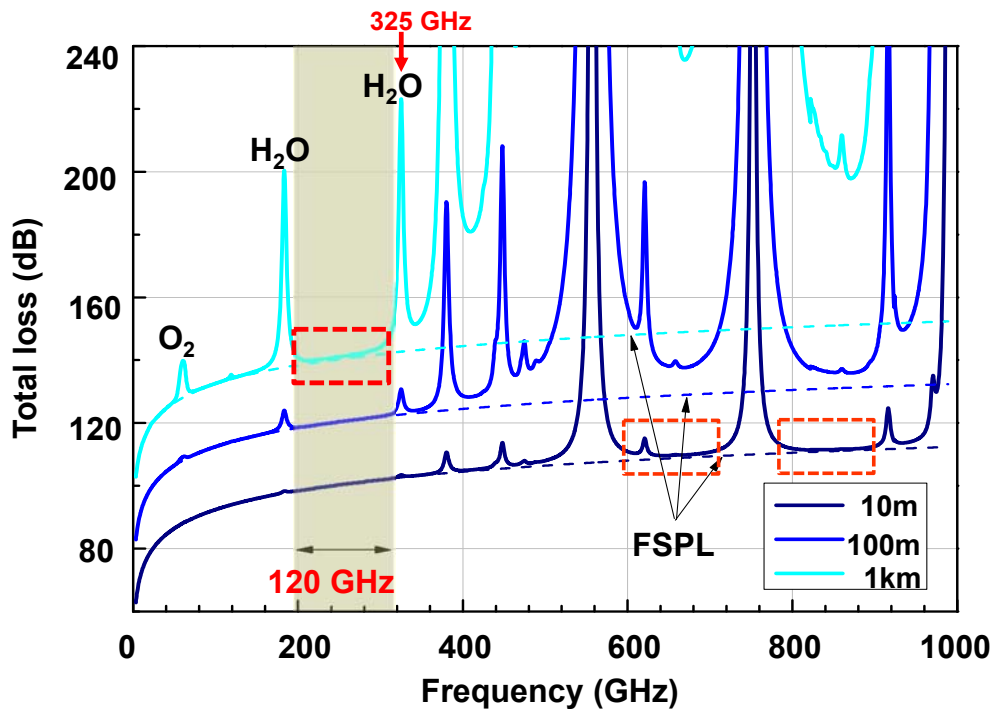


$$\text{loss} \propto 4\pi r^2 / A_e$$

A_e : antenna aperture
 $= \lambda^2 G_a / 4\pi$
 G_a : antenna gain

The above equation is for the case when $G_a = 1$ (0 dBi)

Best Window at 200GHz~320GHz



Results of WRC 2019 on THz Communications

Frequency (GHz)	Status in Radio Regulations
252-275 (23)	Allocation for land mobile and fixed service on a co-primary basis
275-296 (21) 306-313 (7) 318-333 (5) 356-450 (94)	Identification for use for the implementation of land mobile and fixed service according to FN 5.564A. No specific conditions are necessary to protect Earth exploration-satellite service (passive) applications.
296-306 (10) 313-318 (5) 318-356 (38)	may only be used by fixed and land mobile service applications when specific conditions to ensure the protection of Earth exploration-satellite service (passive) applications are determined in accordance with Resolution 731 (Rev.WRC-19).

Most Promising H Band for Beyond 5G

- **Window** determined by wave propagation
- **Standardized** in IEEE802.15
- **Identification** at WRC2019

👉 **252~296 GHz**
Center frequency: 274 GHz
Bandwidth: 44 GHz

30 Gbit/s with ASK (OOK)
90 Gbit/s with PAM8
>100 Gbit/s with 16QAM and 32QAM
>200 Gbit/s with 256QAM

State-of-the-art Semiconductor Electronics

Compound semiconductor (III/V) ICs

25nm InP HEMT, $f_{max}=1.5\text{THz}$,
(9-dB >1-THz amp)
GaN, $f_{max}=0.58\text{ THz}$
InP-GaAsSb DHBT, $f_{max}=1.18\text{ THz}$

Si-semiconductor ICs

CMOS bulk/SOI/FinFETs,
 $f_{max}\approx 300\text{-}450\text{ GHz}$
(20nm~60nm node,
3nm applicable recently)
SiGe BiCMOS/SiGe HBT,
 $f_{max}\approx 700\text{GHz}$ (100~150nm)

Heterogeneous integration

InP + SiGe
InP + SiC

Electronic-photonic integration

Optical modulator/optical waveguide/
Ge photodiode/ on Silicon

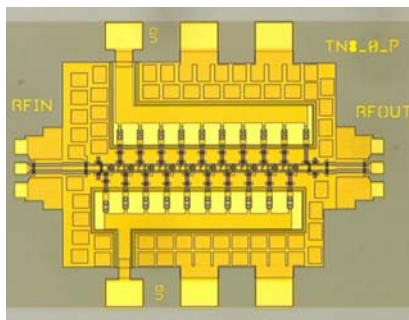
Different Approach: InP/GaAs vs. Si (@>300 GHz)

Material	Tr performance	Configuration of transmitter
InP/GaAs	$f_{RF} < f_{max}$	
Si	$f_{RF} > f_{max}$	

Capability of InP ICs: 1-THz Amplification

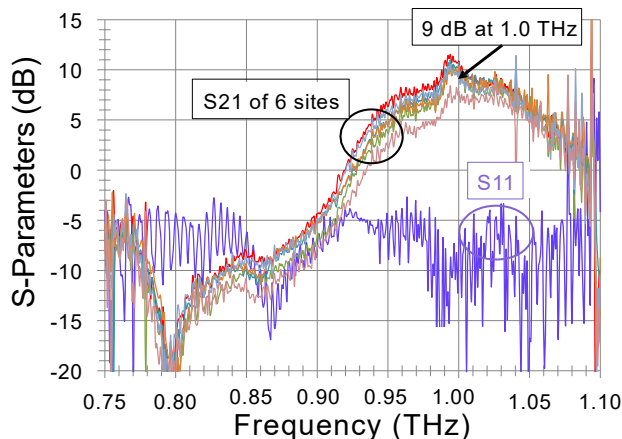
X. Mei, et al., "First Demonstration of Amplification at 1 THz using 25-nm InP High Electron Mobility Transistor Process," *IEEE Electron Dev. Lett.*, 36, pp. 327–329 (2015).

- **25-nm InP HEMT**
- **10-stage common source**
- **2-finger 8- μ m wide devices**



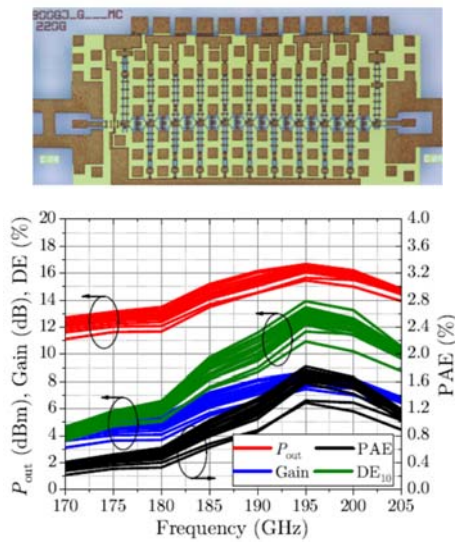
(Substrate thickness: 25 μ m)

9 dB Gain demonstrated on wafer at 1 THz



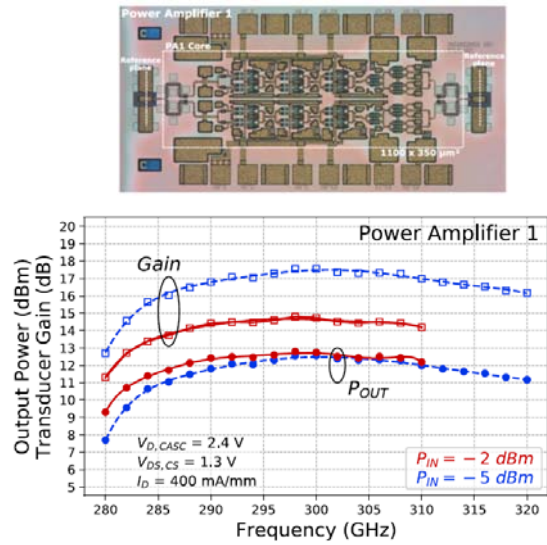
Practical Amplifiers by Compound Semi

GaN G-band (140–220 GHz)



M. Ćwikliński et al., 2020 IEEE/MTT-S IMS.

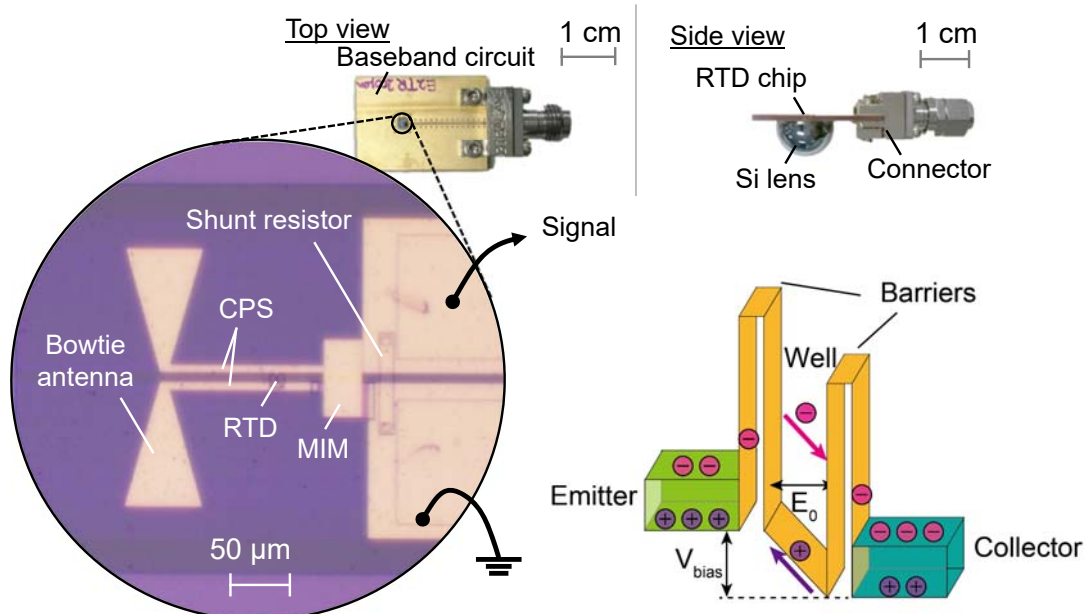
InGaAs mHEMT 300 GHz



L. John et al., IEEE Trans. THz Science Tech., vol. 10, no. 3, pp. 309-320, 2020

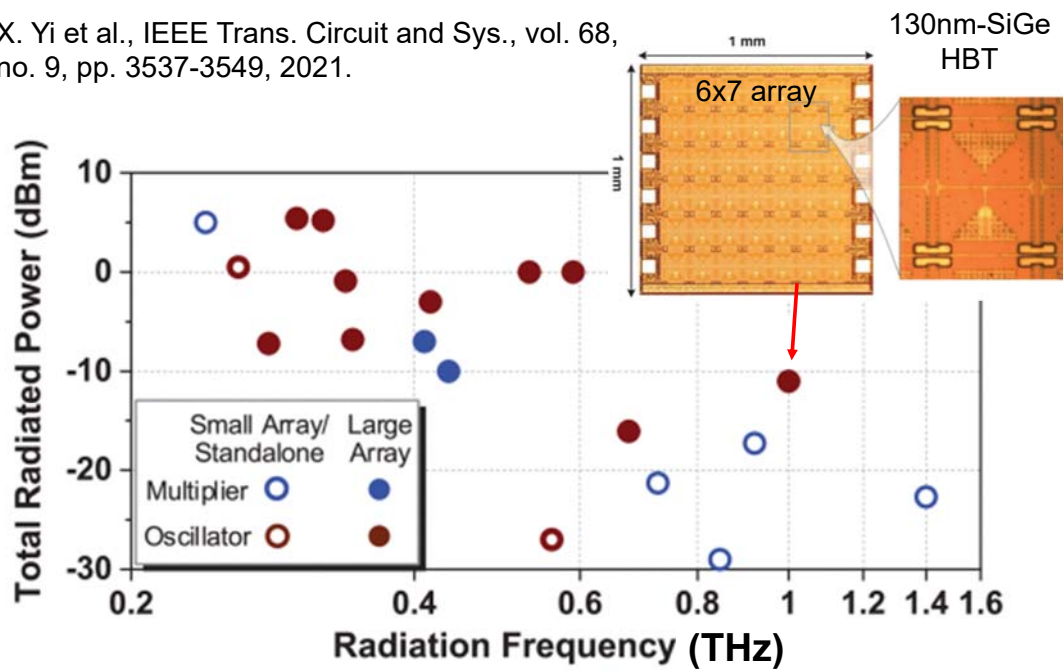
Resonant Tunneling Diode “THz Dark Horse”

RTD: Resonant tunneling diode



Si Way: Array Oscillators

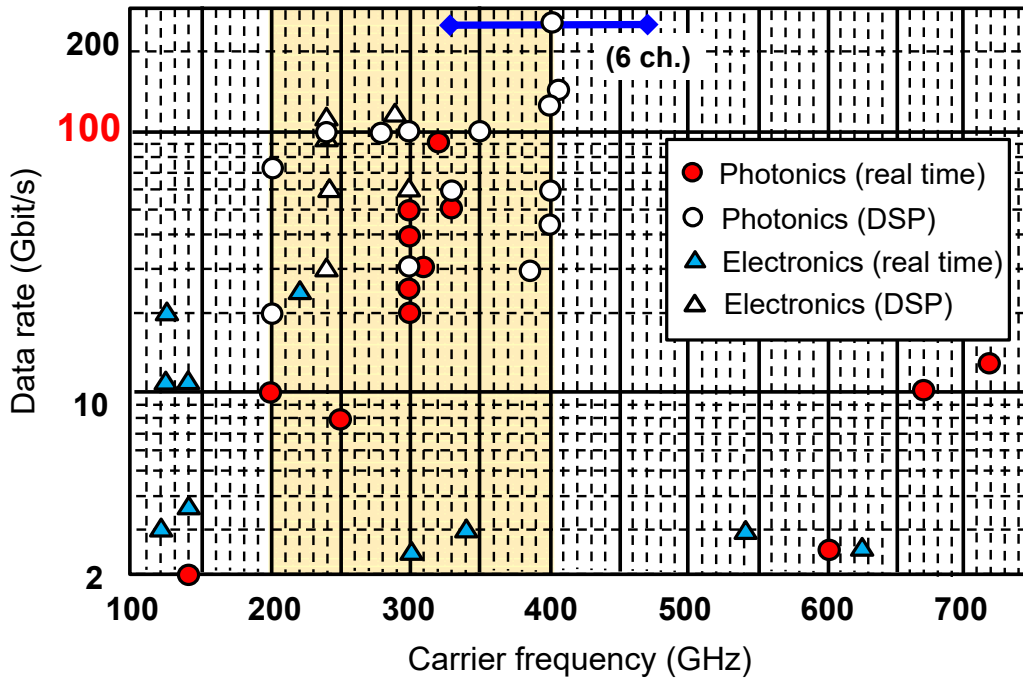
X. Yi et al., IEEE Trans. Circuit and Sys., vol. 68, no. 9, pp. 3537-3549, 2021.



Required Data Rate for B5G/6G

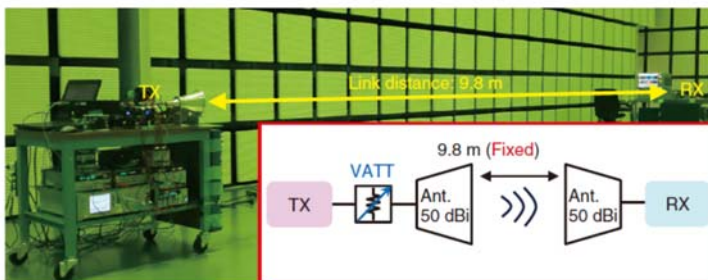
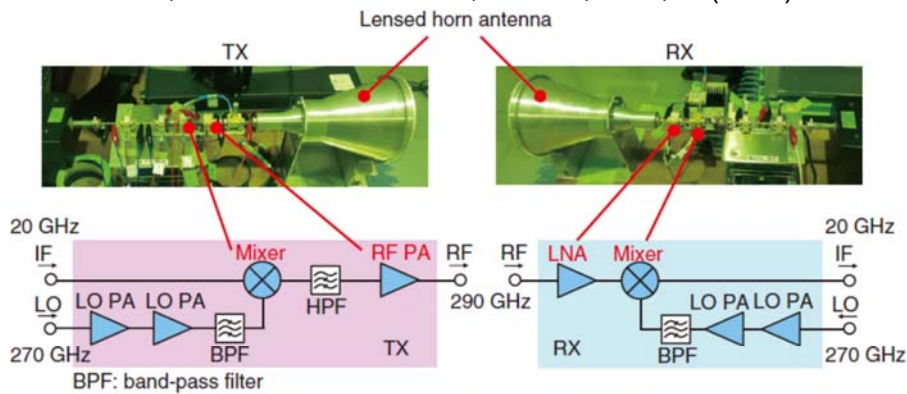
2000	2010	2020	2030
100M bit/s	1G bit/s	10G bit/s	100G bit/s
3G	LTE/4G	5G	6G

Recent Results: Carrier vs. Data Rate



300-GHz-band InP-HEMT ICs (NTT)

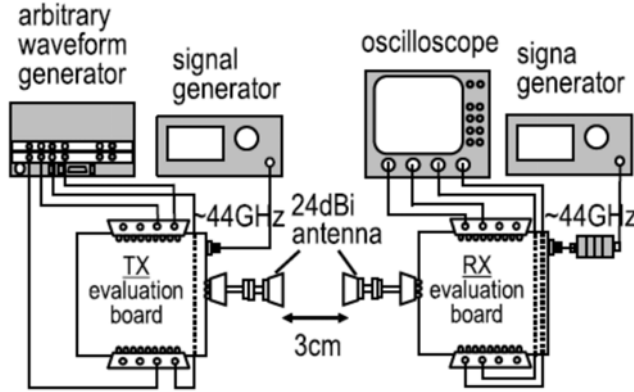
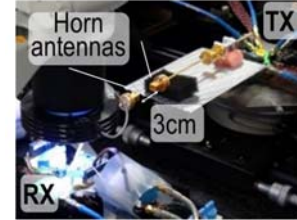
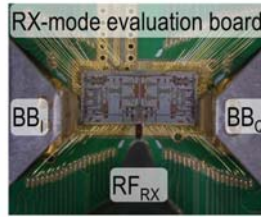
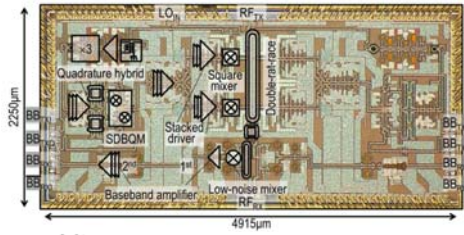
H. Hamada et al., NTT Technical Review, Vol. 19 ,No. 5, 74(2021).



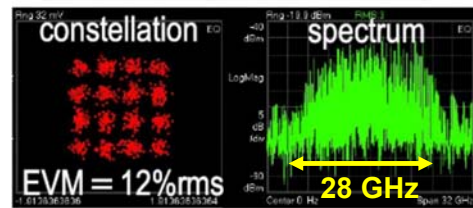
**80-nm InP HEMT
Mixers and amplifiers
290+/-24 GHz
16QAM, 30Gbaud
120Gbit/s, 9.8 m**

300-GHz-band Si-CMOS ICs (Hiroshima U.)

M. Fujishima et al., IEICE Electronics Express, Vol.18, No.8, 1–7, 2021.

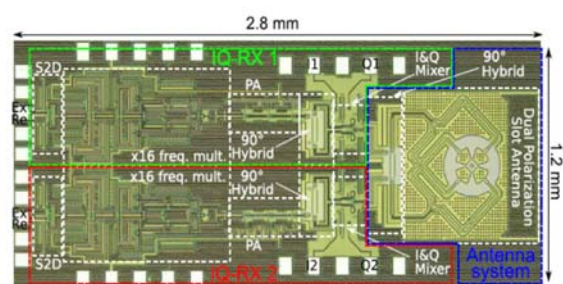
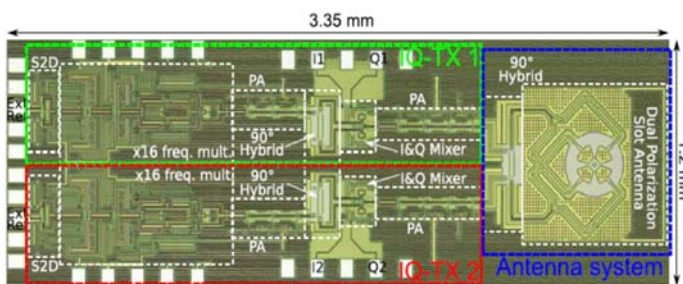


Carrier Frequency	265.68GHz
Modulation	Ch66 in 802.15.3d
Symbol Rate	16QAM
Output Power	20GBaud
Power Consumption	-1.6dBm
	1.79W



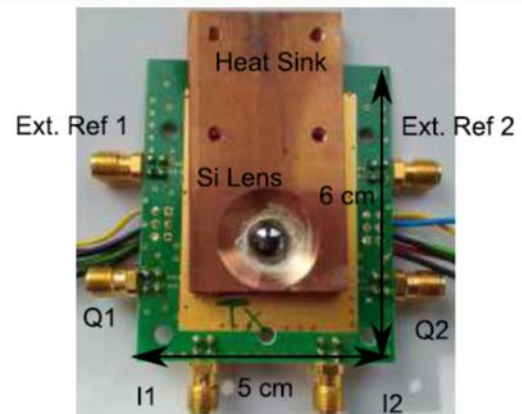
16QAM, 20 Gbaud, 80 Gbit/s, 3 cm

240-GHz-band SiGe HBT ICs(U. Wuppertal)



110 Gbit/s (QPSK+ pol. Mux)

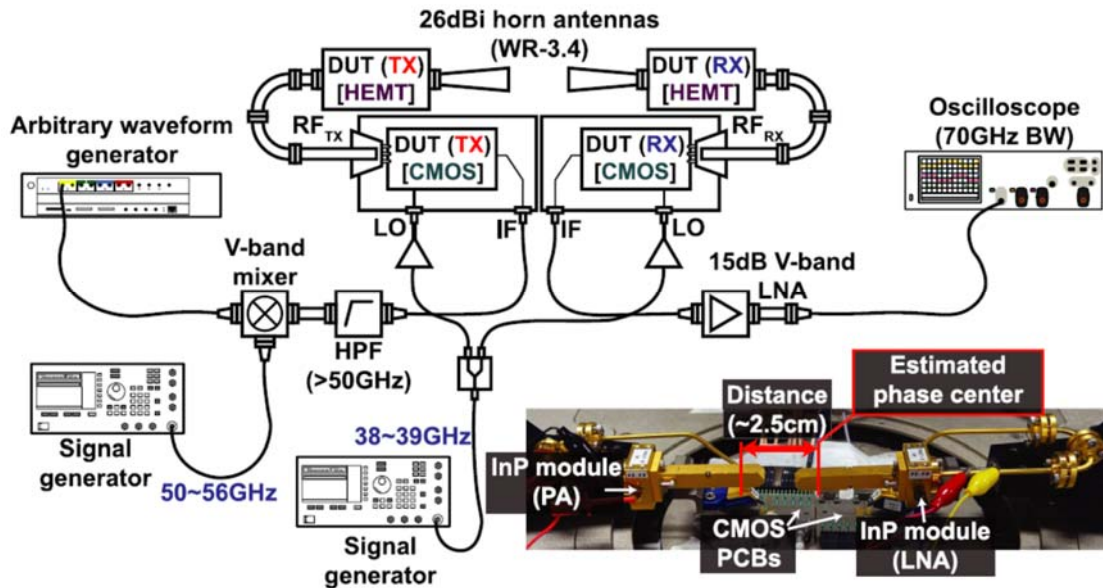
P. Rodríguez-Vázquez et al., "A QPSK 110-Gb/s Polarization-Diversity MIMO Wireless Link With a 220–255 GHz Tunable LO in a SiGe HBT Technology," IEEE Trans. MTT, pp. 3834-3851, September 2020.



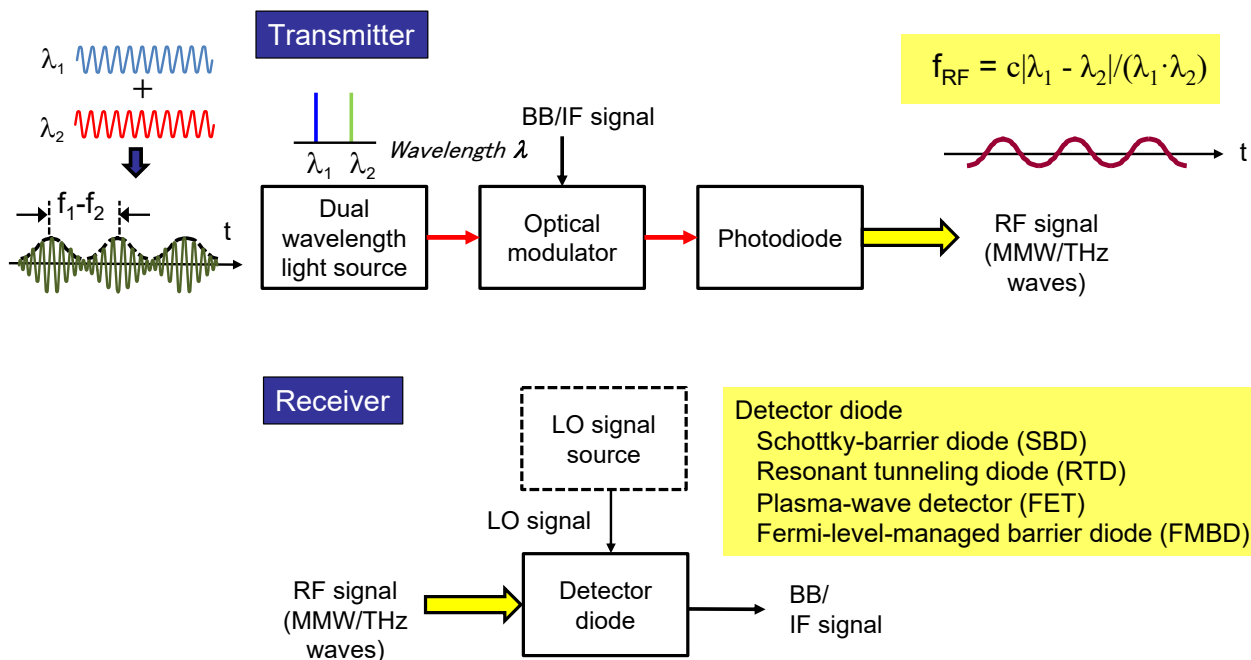
300-GHz-band InP-CMOS Hybrid (Titech·NTT)

I. Abdo et al., IEICE Electronics Express, Vol.18, No.17, pp.1–4 (2021).

278-304GHz: 56 Gbit/s (16QAM)

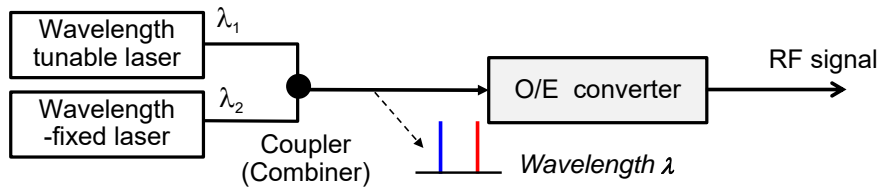


Basic Configuration: Photonics for CW Transmitters

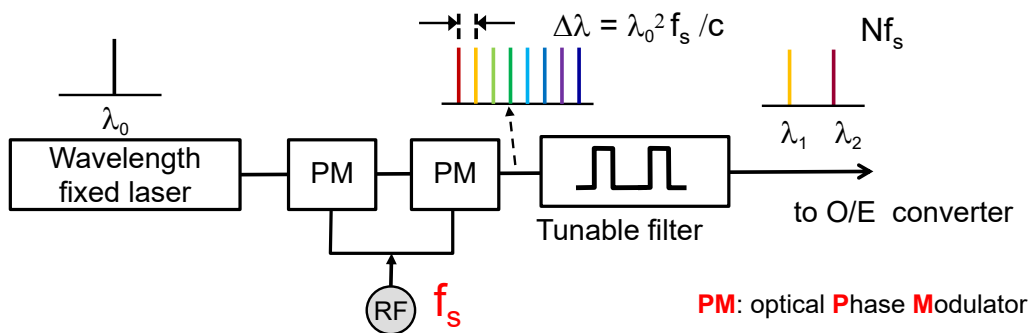


CW Optical MM/THz-wave Sources

Basic scheme



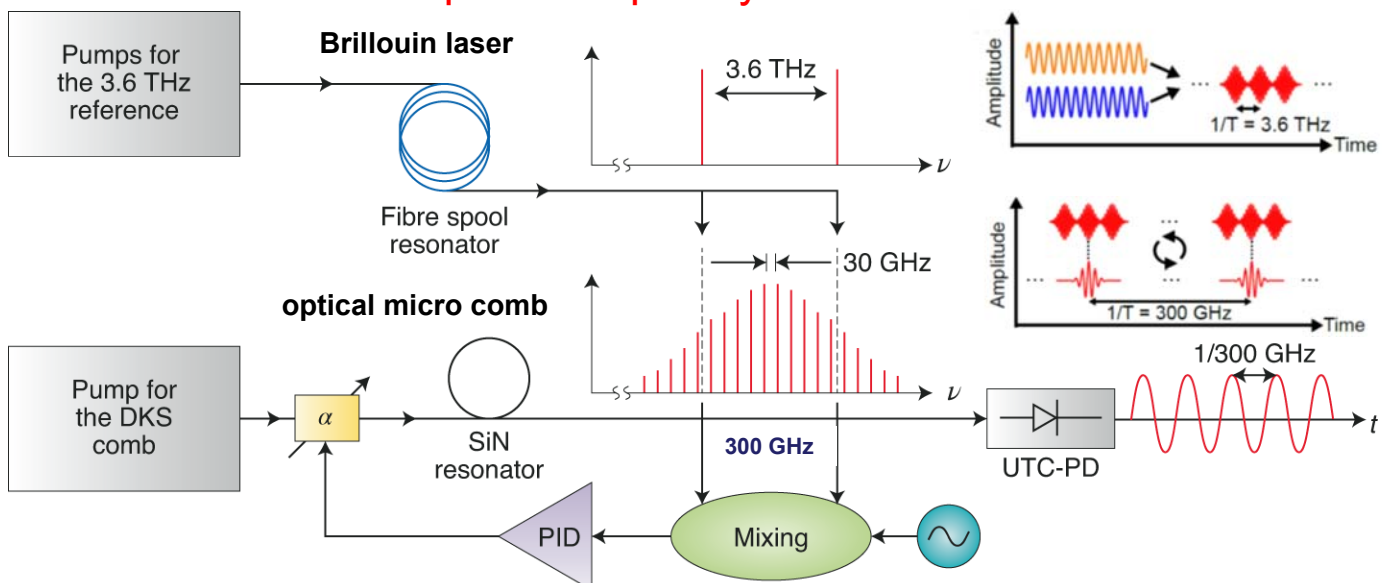
Highly Coherent Sources using Optical Frequency Comb



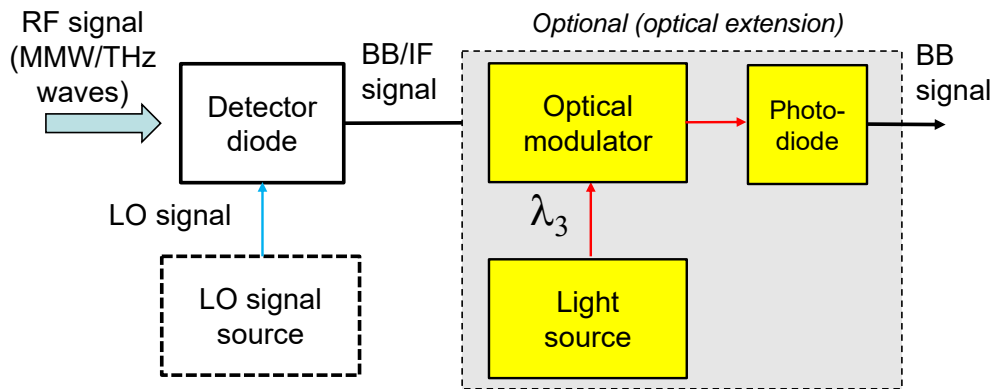
Ultra-low Phase Noise Optical Signal Generation

T. Tetsumoto, T Nagatsuma et al., "Optically referenced 300 GHz millimetre-wave oscillator," Nature Photonics, 2021.

"optical frequency division"



Typical Receiver Configurations

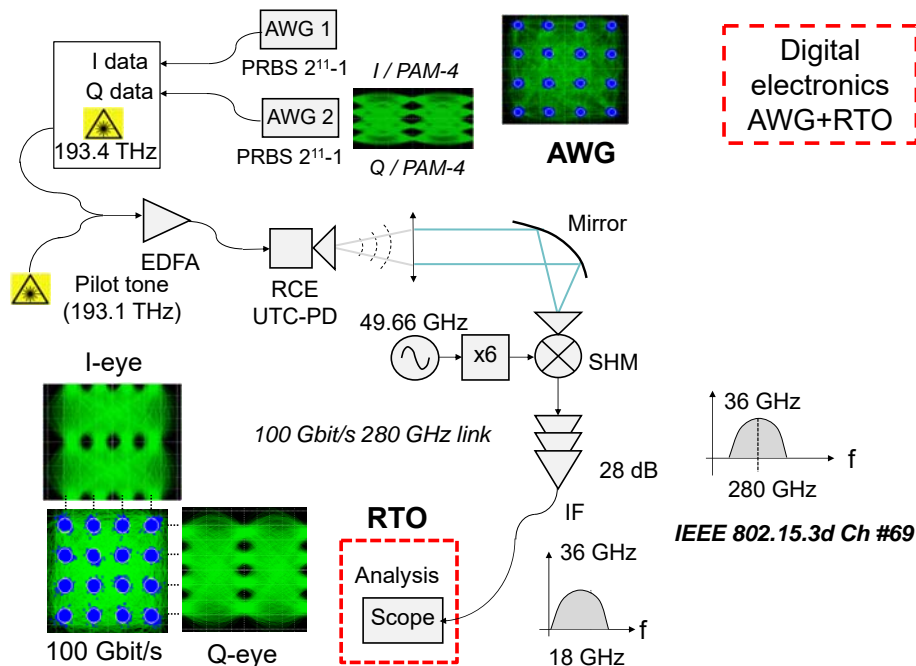


Detector diode

- Schottky-barrier diode (SBD)
- Resonant tunneling diode (RTD)
- Plasma-wave detector (FET)
- Fermi-level-managed barrier diode (FMBD)

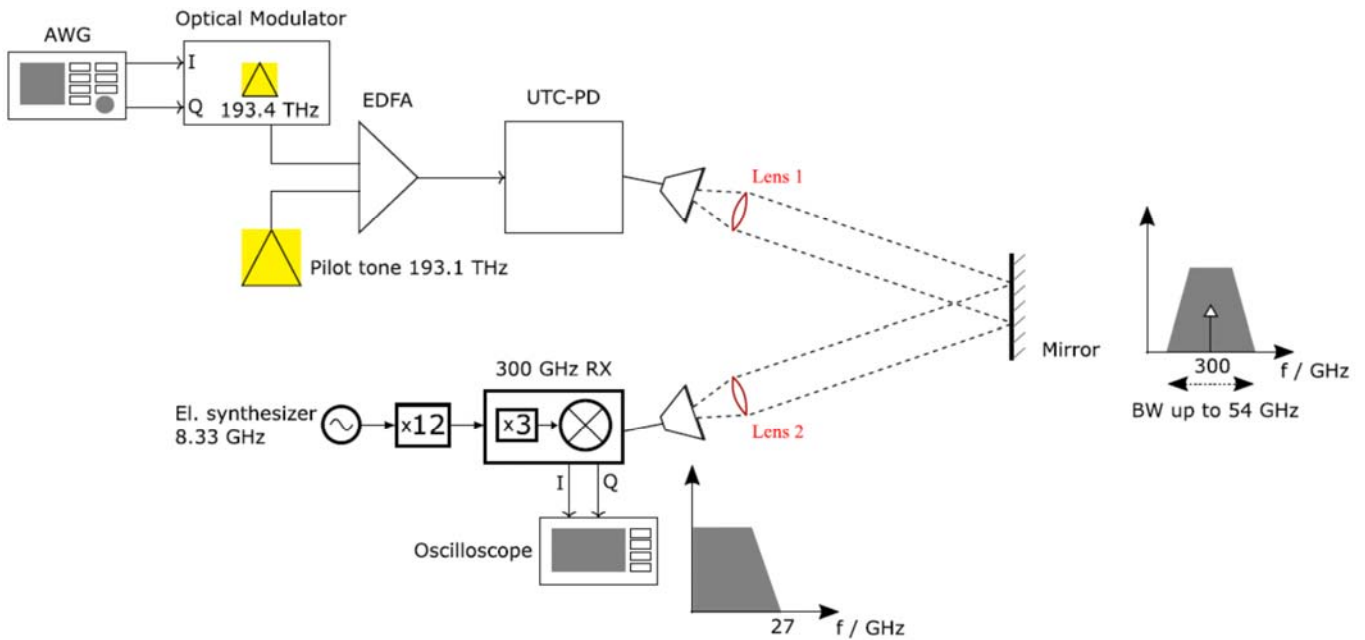
Free-running Transmitter and Heterodyne Receiver

V. K. Chinni *et al.*, *Electron. Lett.*, 54, 10, pp. 638-640, March 2018.



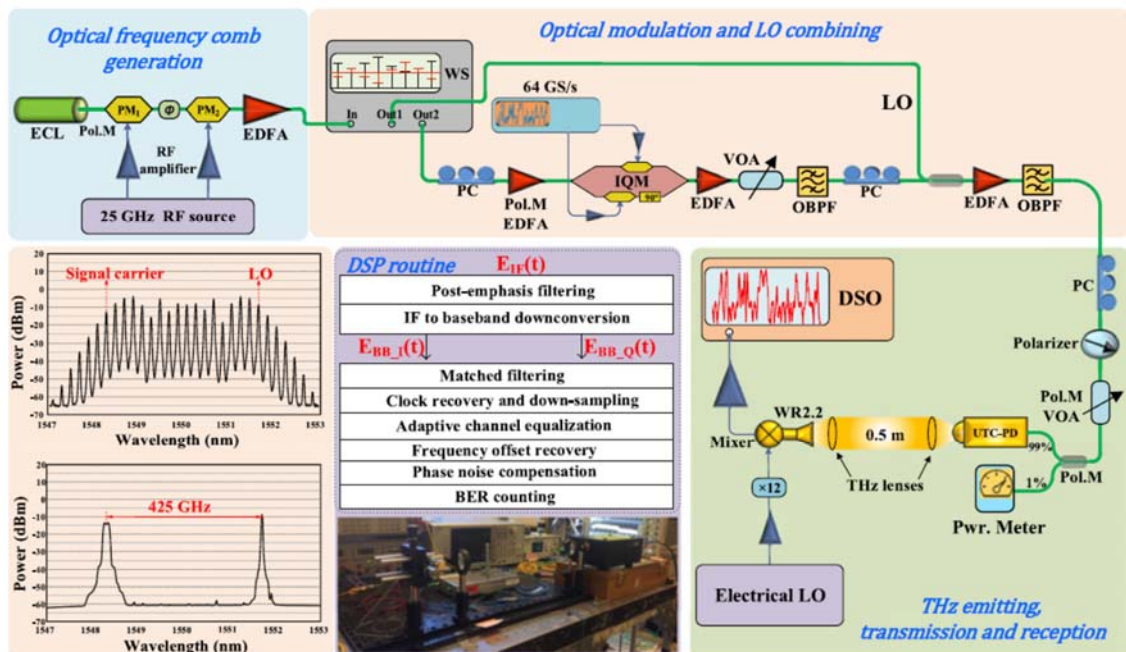
Free-running Transmitter and Direct I/Q Receiver

I. Dan *et al.*, *Trans. Terahertz Science Tech.*, **10**, 3, pp. 271-281, May, 2020.



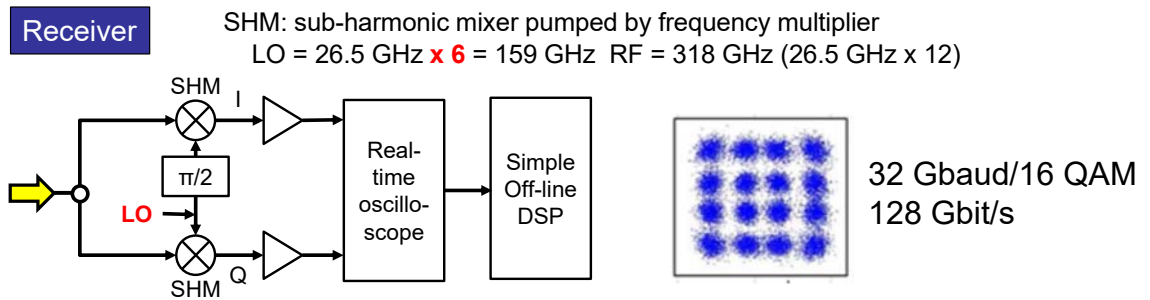
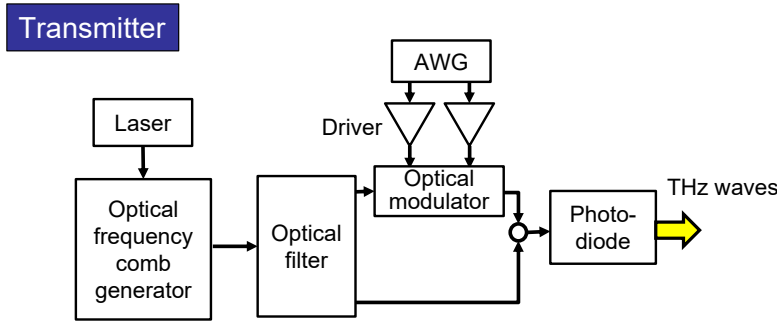
Frequency-stabilized Transmitter and Heterodyne Receiver

S. Jia *et al.*, *J. Lightw. Technol.*, **36**, 2, pp. 610-616, Jan. 2018.

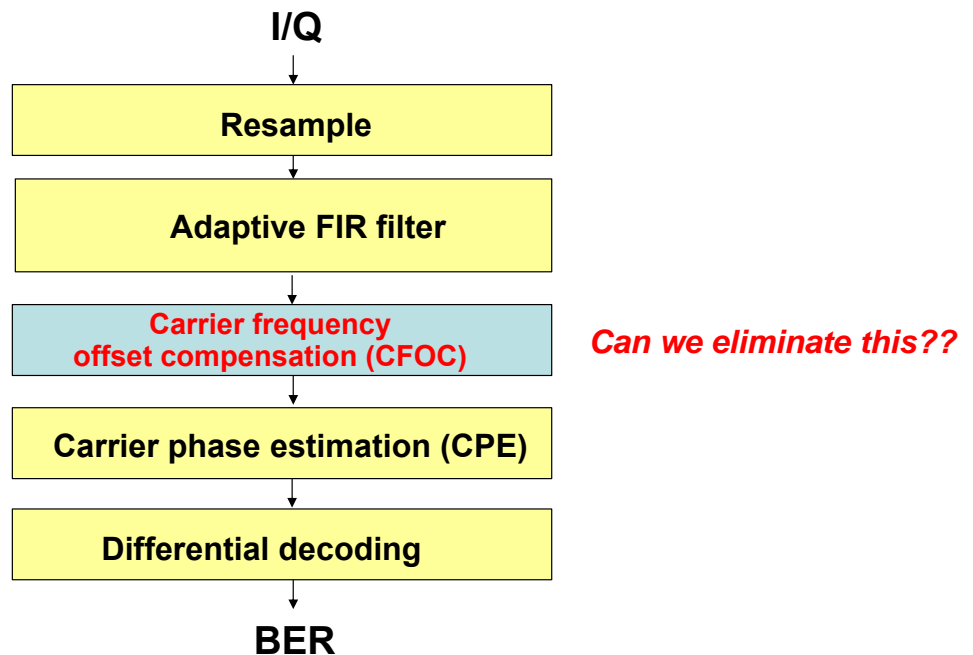


Frequency-stabilized Transmitter and Direct I/Q Receiver

T. Nagatsuma *et al.*, URSI AT-AP-RASC2022, Tu-D01-PM2-1, May 2022.

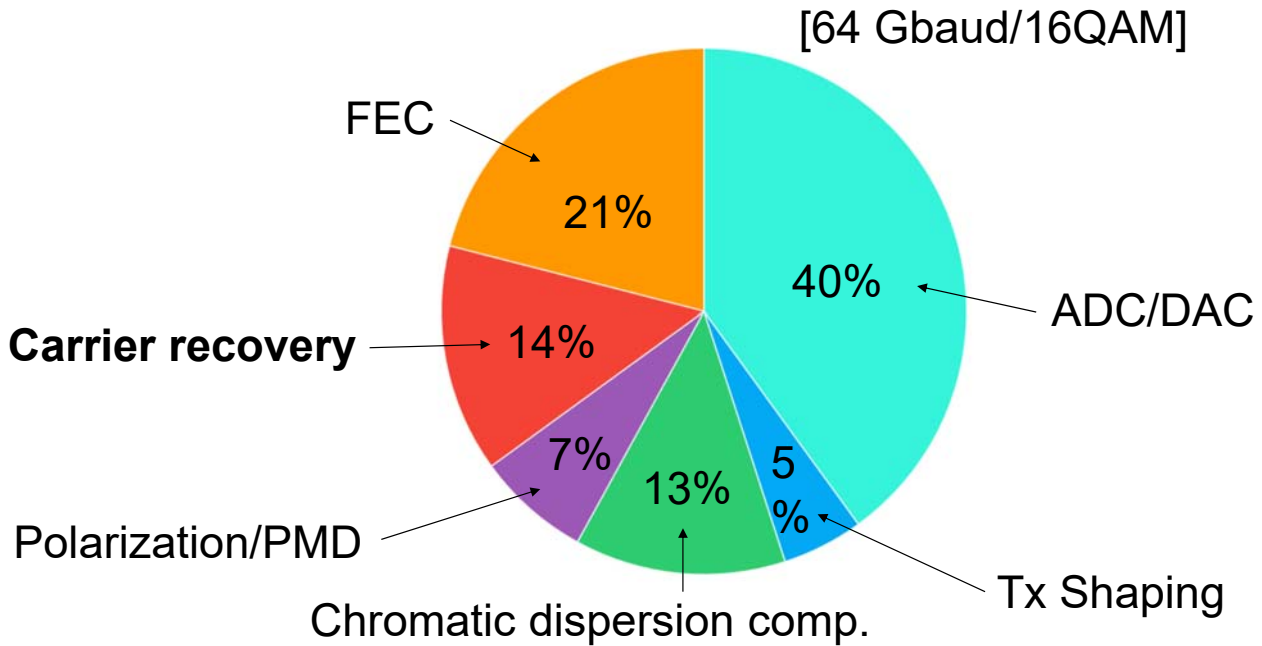


Standard Simplest Off-line DSP



Increase in DSP Power Dissipation

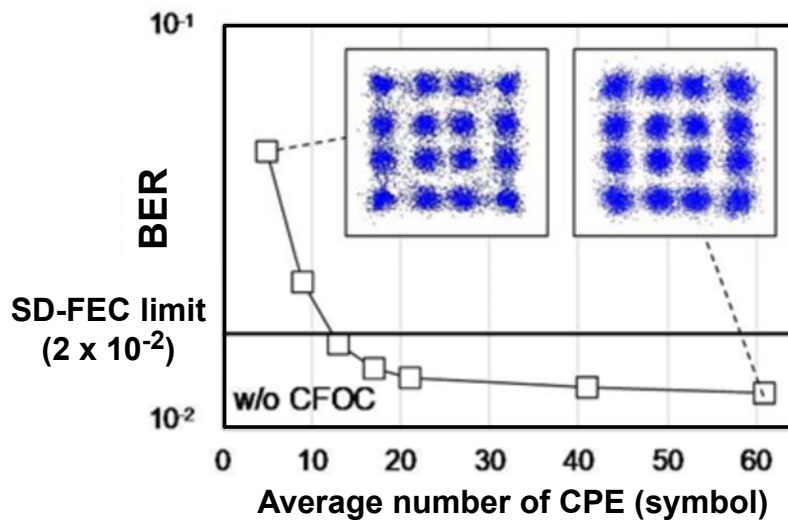
T. Kupfer et al., "Optimizing Power Consumption of a Coherent DSP for Metro and Data Center Interconnects," Th3G.2, OFC2017.



Effect of CFOC & CPE

CFOC: Carrier frequency offset compensation

CPE: Carrier phase estimation

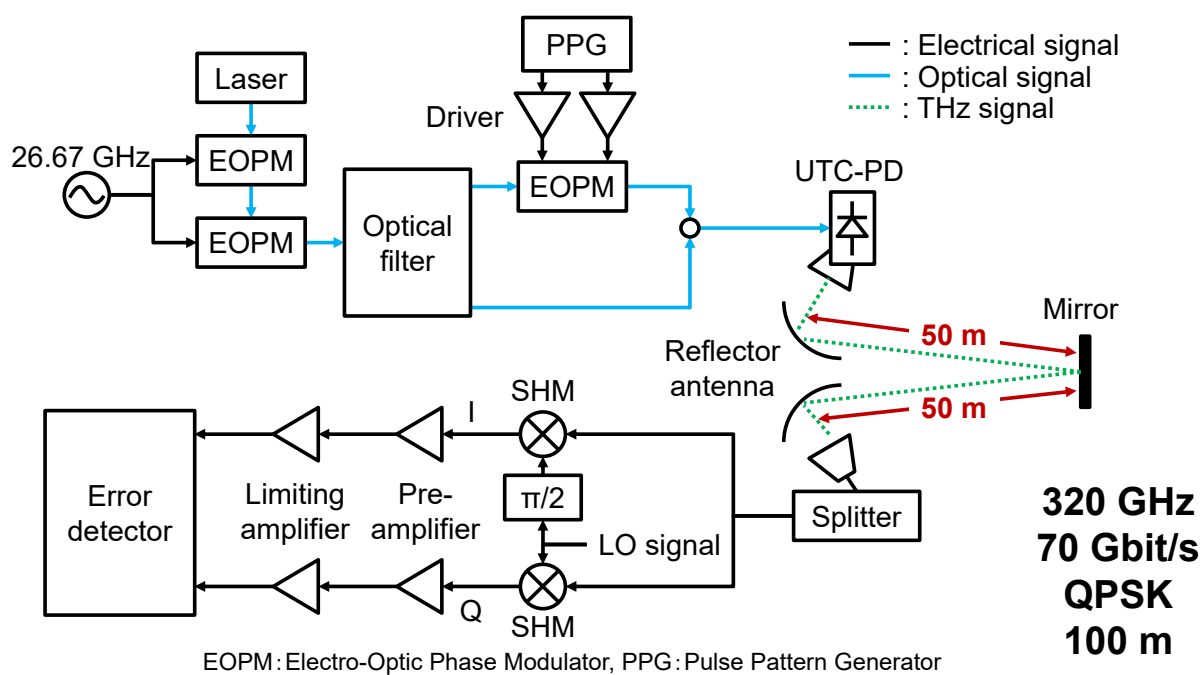


CFOC is not necessary!!

Link Distance Challenge/SISO

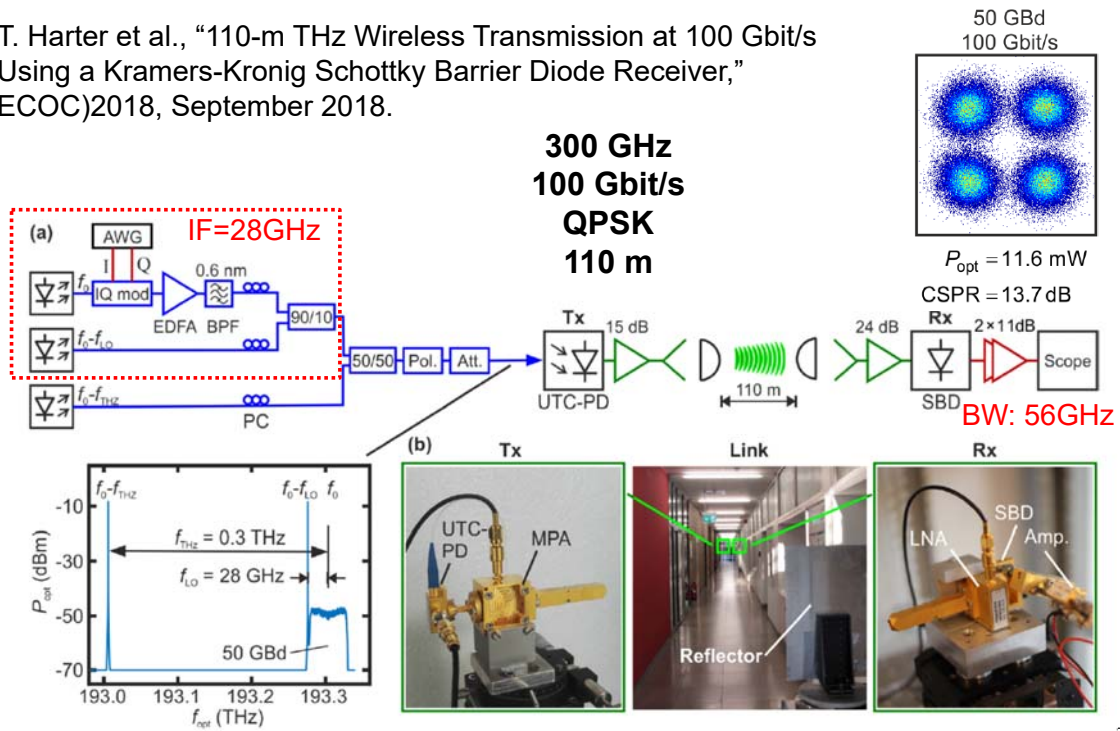
Carrier	Data rate	Distance	Ref.
125 GHz (18GHz)	10 Gbit/s (OOK/real time)	5.8 km	A. Hirata et al., ICWITS 2010
240 GHz	64 Gbit/s (QPSK/off line)	850 m	I. Kalfass et al., J. IRMMW/THz, 2015
320 GHz	70 Gbit/s (QPSK real time)	100 m	K. Iwamoto et al., MTSA 2017
300 GHz	100 Gbit/s (QPSK /off line)	110 m	T. Harter et al., ECOC 2018
300 GHz	44 Gbit/s (QPSK /off line)	1 km	C. Castro et al., IWMTS 2020

QPSK 100-m Transmission at 320GHz (OU)

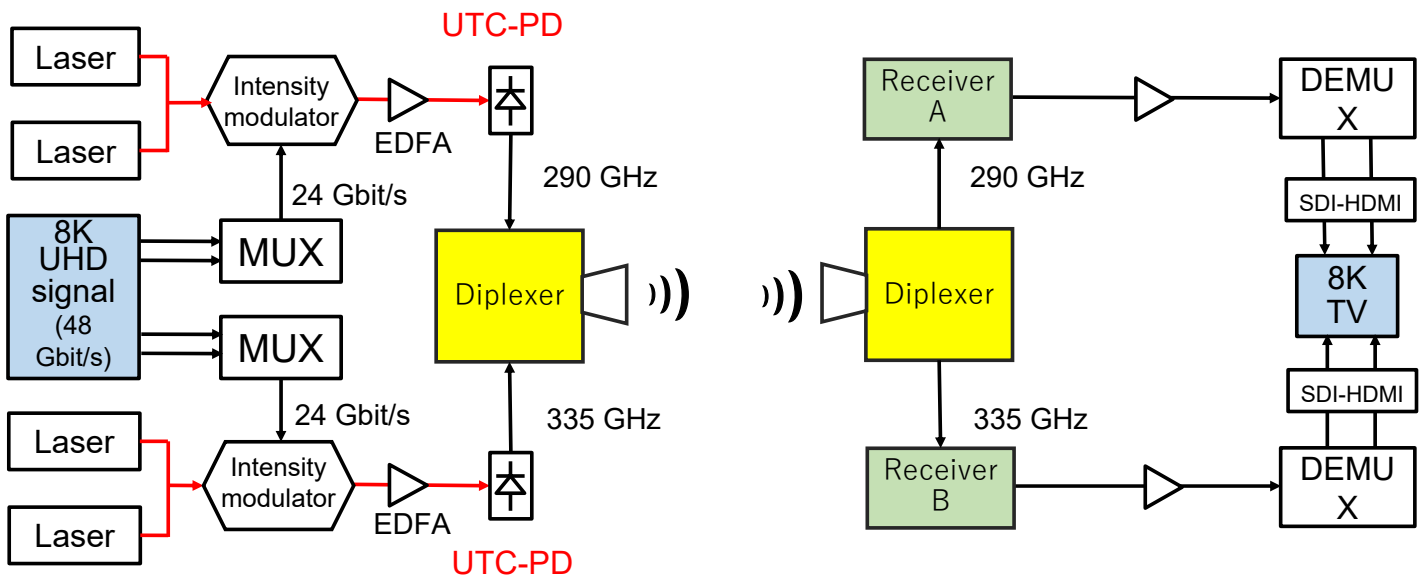


QPSK 100-m Transmission at 300 GHz (KIT)

T. Harter et al., "110-m THz Wireless Transmission at 100 Gbit/s Using a Kramers-Kronig Schottky Barrier Diode Receiver," ECOC'2018, September 2018.



Full 8K Ultra-HDTV Transmission: 48 Gbit/s





We are ready for preparation towards 6G

- 100 Gbit/s has been achieved by using 200-400GHz carriers (G and H bands).
- Most of them utilize photonics technologies, which has led frontend of THz communications research. Now, electronics have been catching up with photonics.
- Over-200-Gbit/s has been reported by using multi-channels based on photonics.
- D-band (110-170GHz) is also promising in terms of device maturity.

Outline

Review current status of THz communications research and discuss the future direction

1. State of the art

- selection of frequencies/bands*
- transceiver and system technologies:
photonics vs. electronics*

2. Future directions

- device technologies***
- system integration technologies
expectation for TERAWAY***

Technical Issues and Challenges

-Components

Transmitter output power increase

thermal management of devices
power combiners

Receiver sensitivity increase

low-barrier diodes, etc.

THz optical modulators

Phased arrays (phase shifter problems) and antennas

Phase noise reduction of oscillators

-Integration and packaging

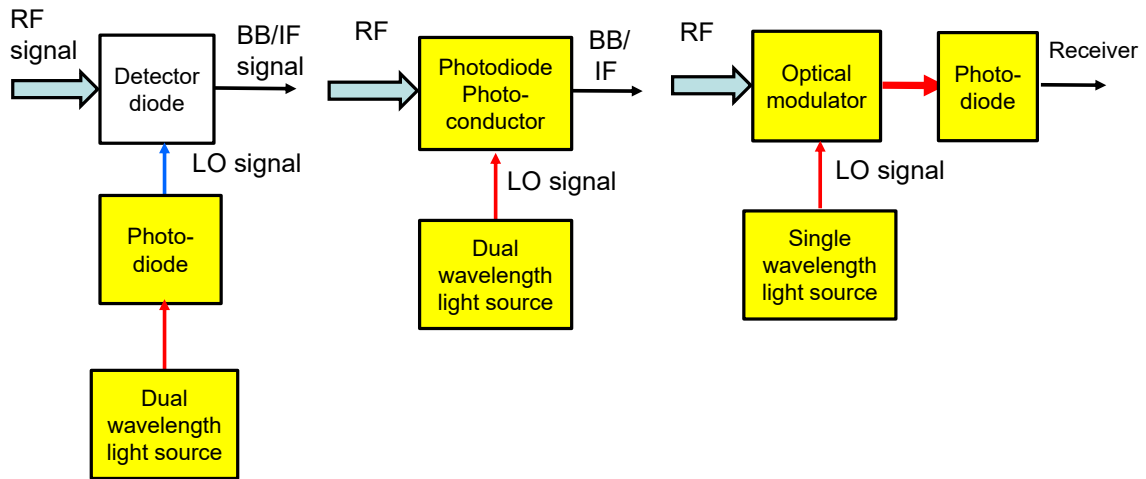
Platform: hollow waveguide, dielectric waveguide

Electronics-photonics integration

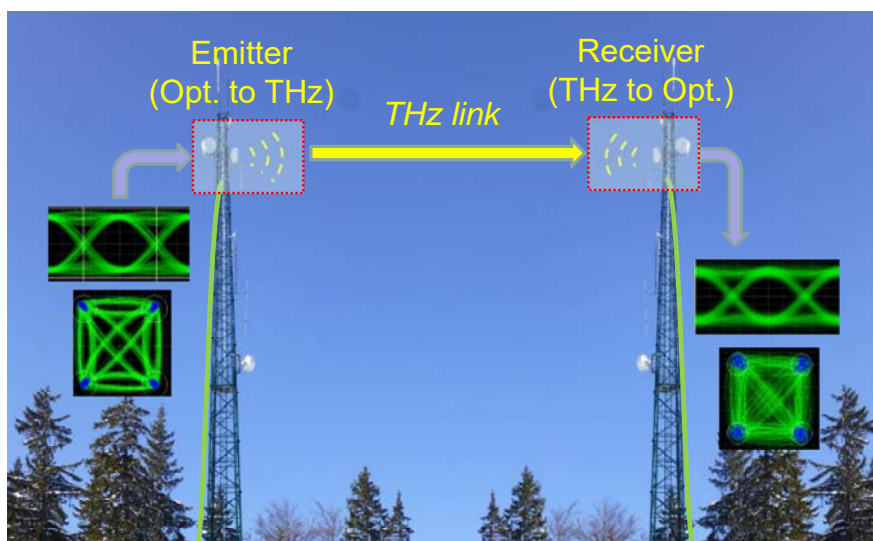
Photonics-based Receivers

Photonics is required more in receivers.

(I) Photonic LO type (II) Photonic receiver type (III) Optical output type



Transparent Optical-THz-Optical Link



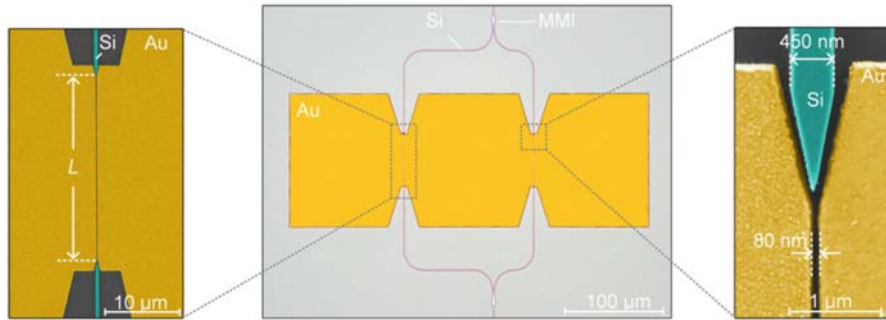
Fiber-optic core networks

Fiber-optic core networks

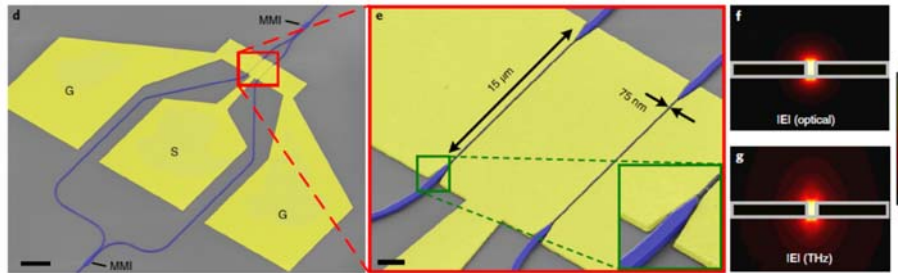
T. Nagatsuma et al., Nature Photonics, vol. 10, 371(2016).

THz Optical Modulators for Reception

W. Heni et al., J. Lightwave Tech., 34, 2, pp. 393-400 (2016).
 M. Burla et al., APL Photon., 4, 056106 (2019).



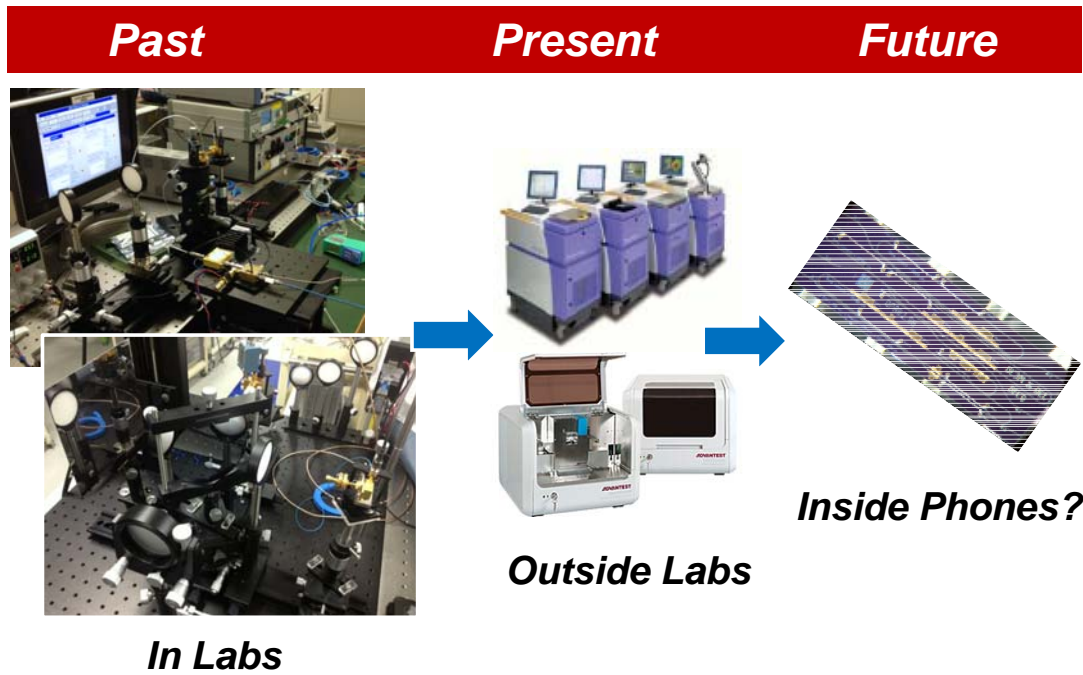
S. Ummethala et al., Nature Photon., 13, pp. 519-524 (2019).



Resent Results for Opt.-THz-Opt. Link

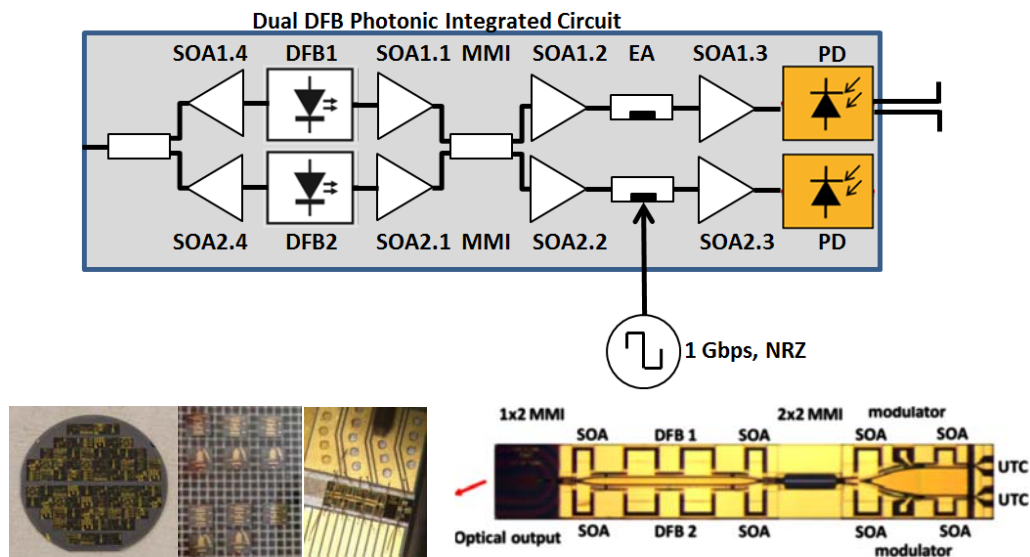
Authors	Frequency	Results	Remarks
S. Ummethala et al. (KIT, 2019)	288.5 GHz	36 Gbit/s (7%FEC) QPSK 16 m	THz preamplifier was used
Y. Horst et al. (ETH, 2021)	230 GHz (79 GHz BW)	190 Gbit/s (10 ch FDM) QPSK & 16QAM 115 m	THz preamplifier was used 20% FEC assumed
P. T. Dat et al. (NICT, 2021)	101 GHz (14 GHz BW)	71 Gbit/s 64QAM 5~20 m	LN modulator was developed 20% FEC assumed

Integration of Photonic Systems



Fully Integrated THz Photonics System

Integrated transmitter for communication (90-100GHz)

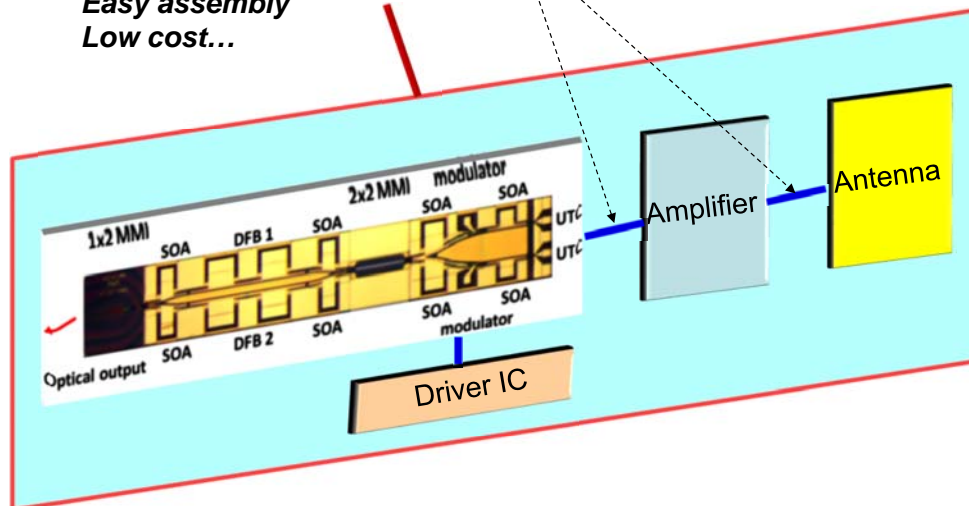


G. Carpintero et al., IEEE Journal of Lightwave Tech., vol. 32, 3495 (2014).

Still Needs Integration/Packaging

Integration platform

Wide bandwidth *interconnect*
Low loss/Low dispersion *interconnect*
Easy assembly
Low cost...



What is the Best THz Transmission Media?

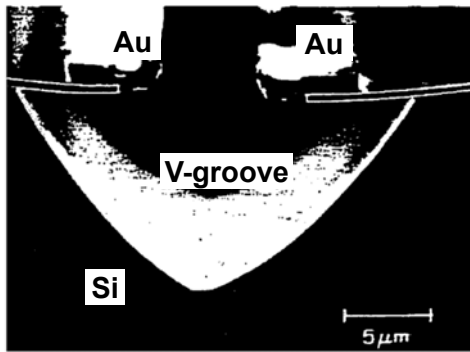
From electronics:

metallic transmission line
metallic hollow waveguide

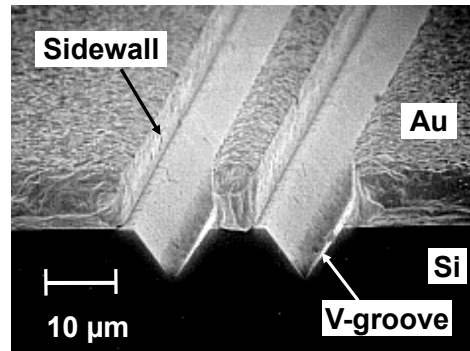
From photonics:

dielectric waveguide

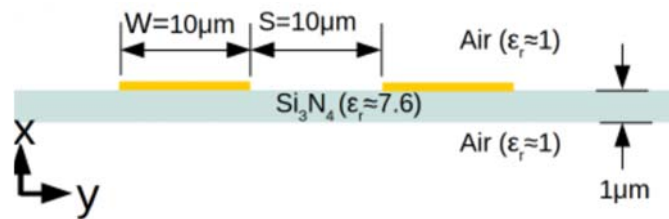
Metallic Lines with Reduced Dielectric Layer



D. R. Dykaar et al., APL, 1990.

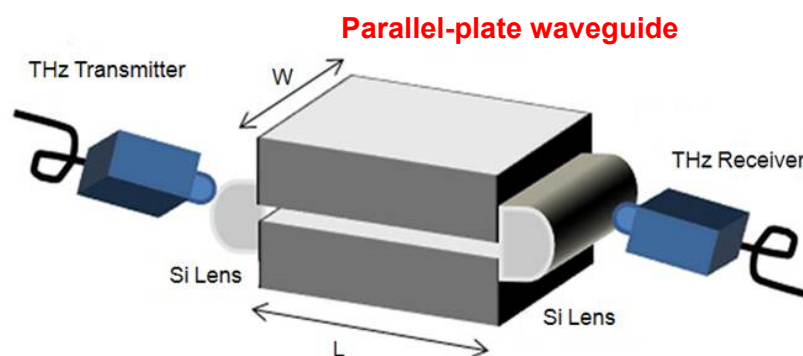


T. Nagatsuma et al., IEEE MTT, 2001.

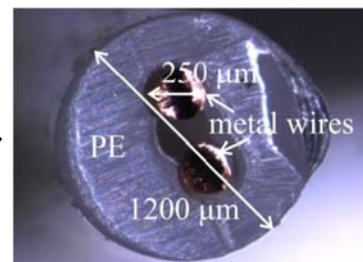
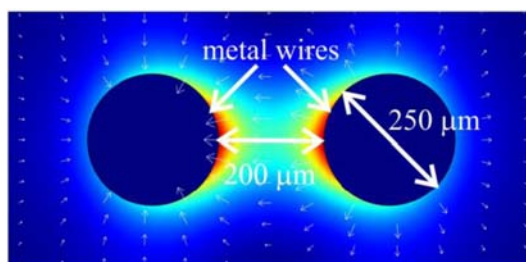


R. Smith et al., Opt. Express, 2019.

Metallic-Line Only is the Best?

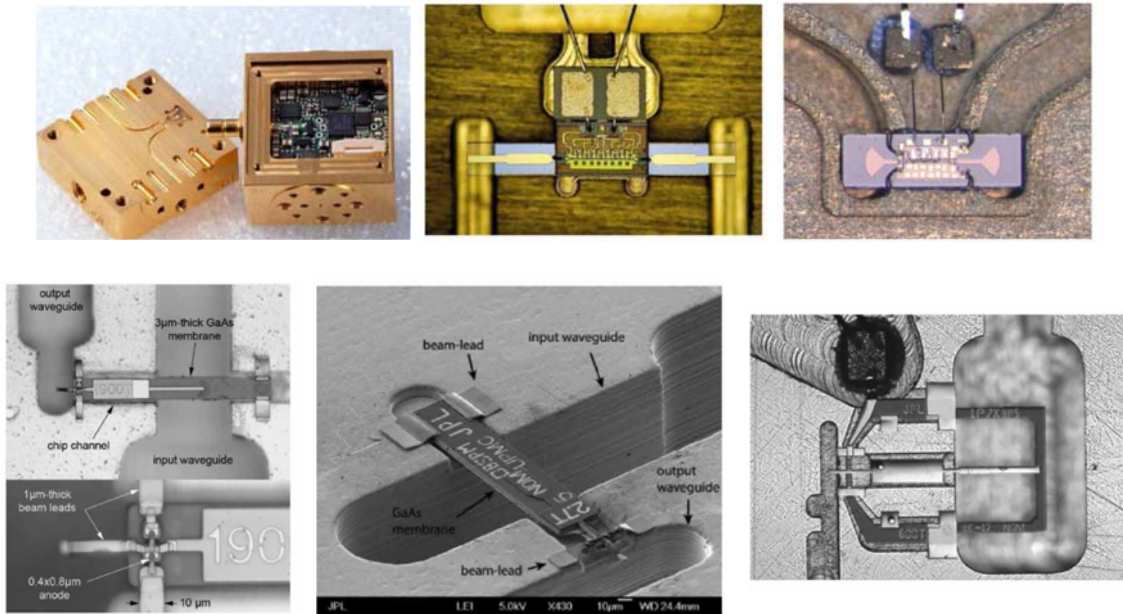


Parallel metal wires



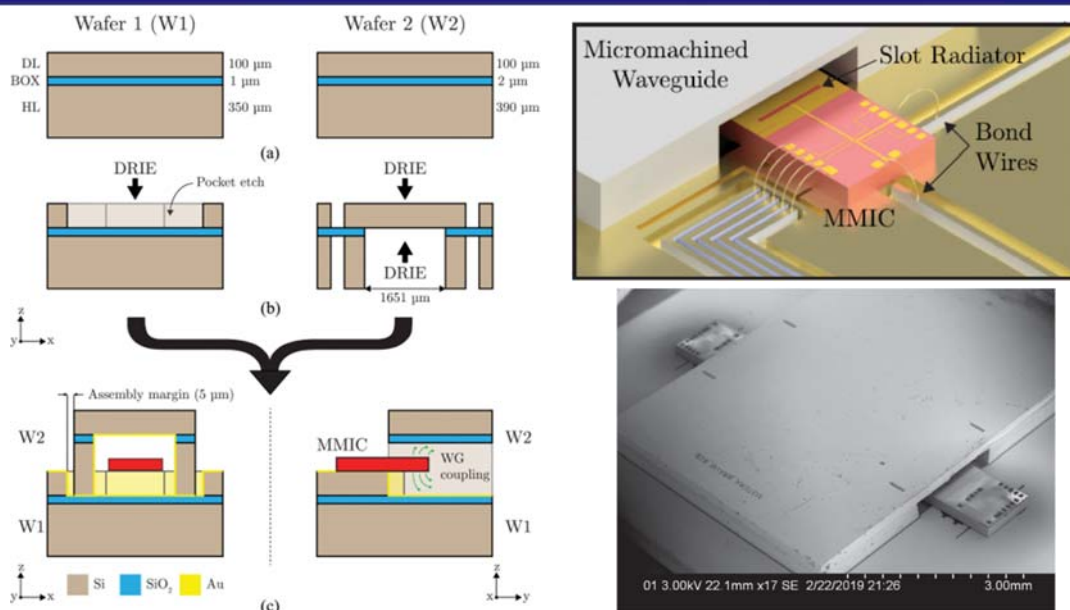
A. Markov et al., J. Opt. Soc. Am., no. 11, Nov.2014.

Packaging in Hollow Waveguides



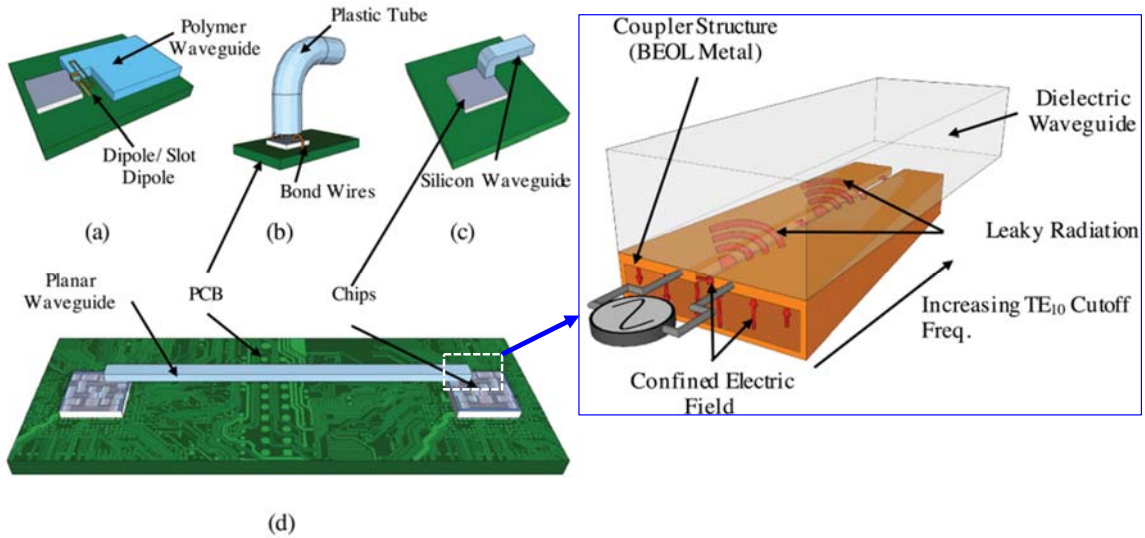
Ho-Jin Song, "Packages for terahertz electronics," Proc. IEEE, 105, 6, 2017.

MEMS-based Hollow-Waveguide Platform



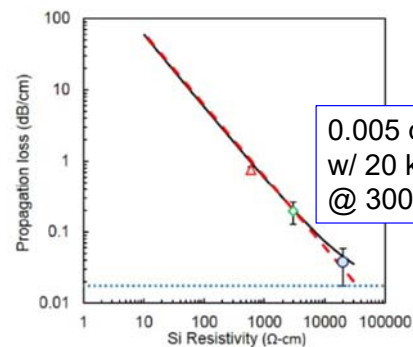
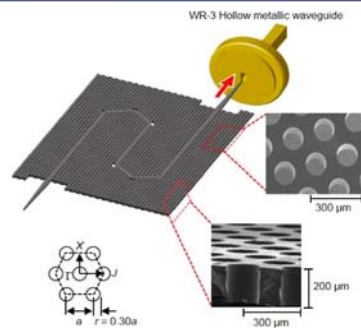
James Campion et al., "Toward industrial exploitation of THz frequencies: integration of SiGe MMICs in **silicon-micromachined waveguide systems**," IEEE Trans. THz Science and Tech., vol. 9, p. 624, (2019): KTH.

Dielectric Waveguide Inspired by Photonics

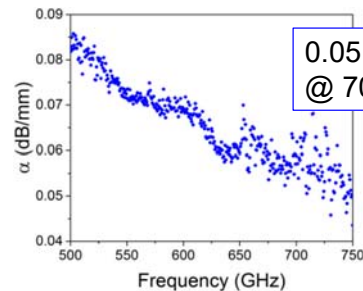
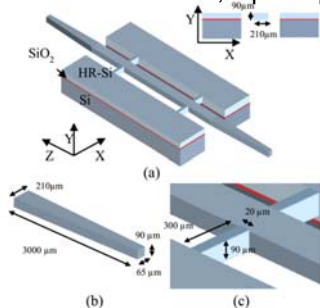


J. W. Holloway et al., "A fully integrated broadband sub-mmWave **chip-to-chip interconnect**," IEEE Trans. Microw. Theory Techn., vol. 65, no. 7, pp. 2373-2386, (2017): MIT.

Dielectric Waveguide Based on Si-MEMS



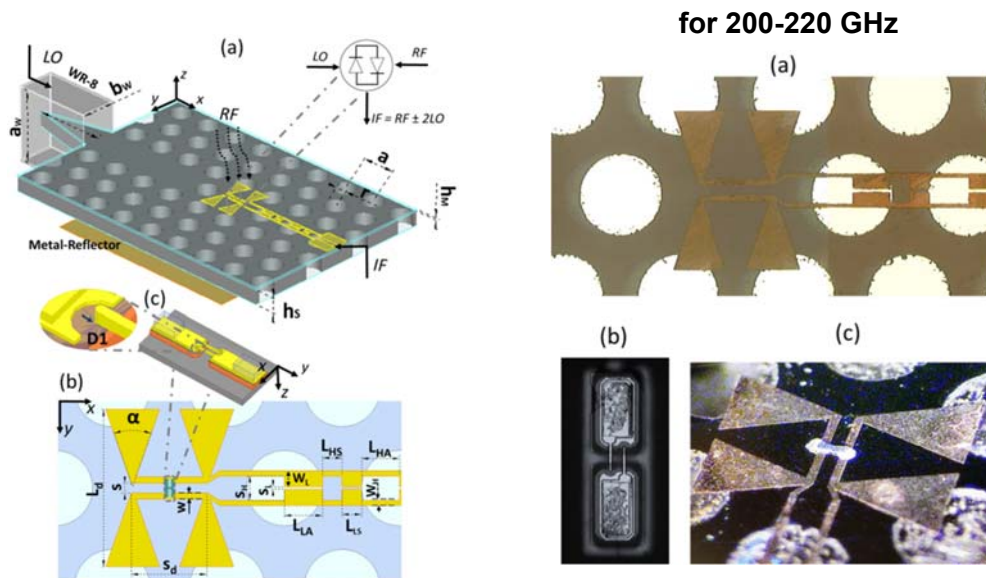
K. Tsuruda et al., Opt. Express, 23, 25, pp. 31977-31990 (2015): Osaka U.



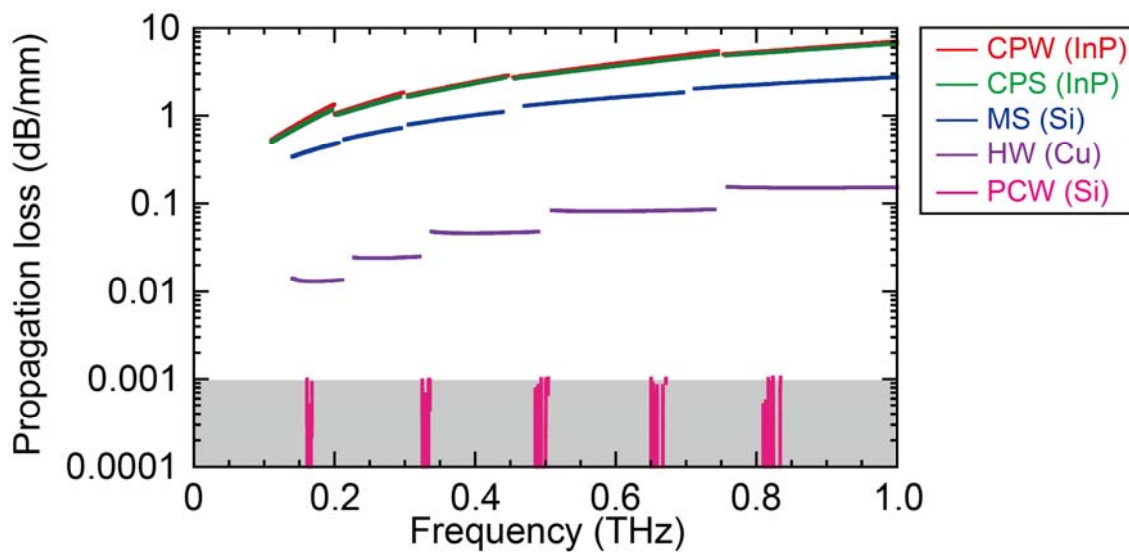
E. Akiki et al., IEEE THz, 11, 1, pp. 42-53 (2021): IEMN.

Example of Integration with Active Devices

A. E. Torres-García et al., "Silicon integrated subharmonic mixer on a **photonic-crystal platform**," IEEE THz, 11, 1(2021): UPNA.

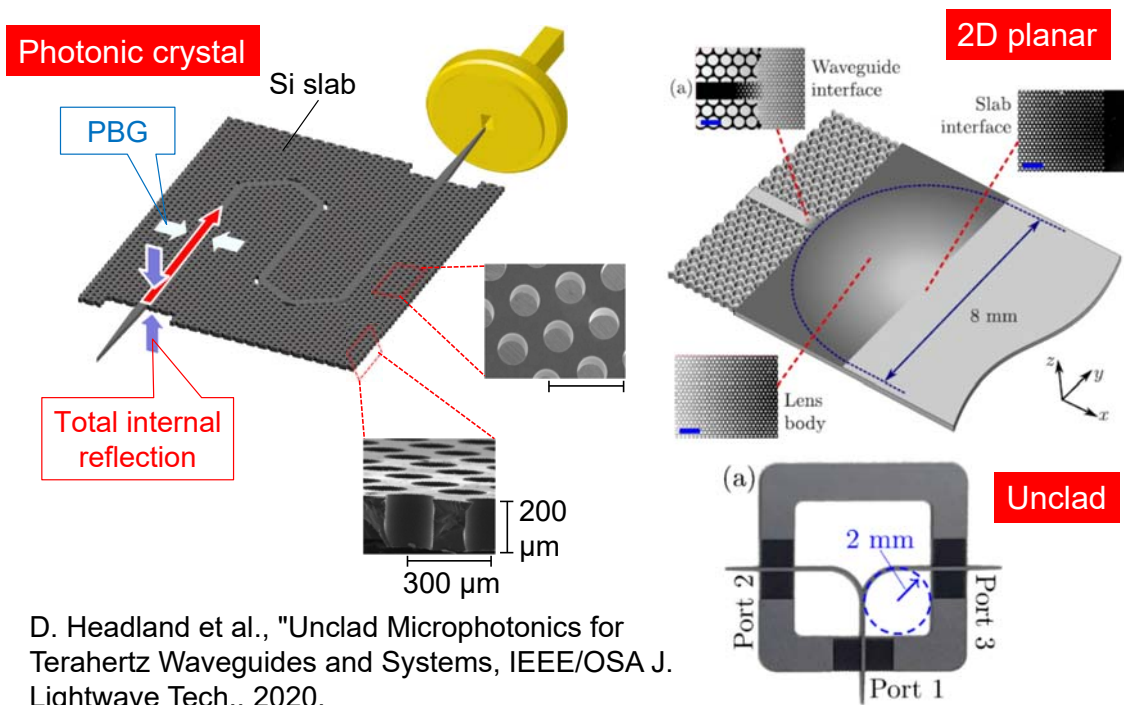


General Comparison

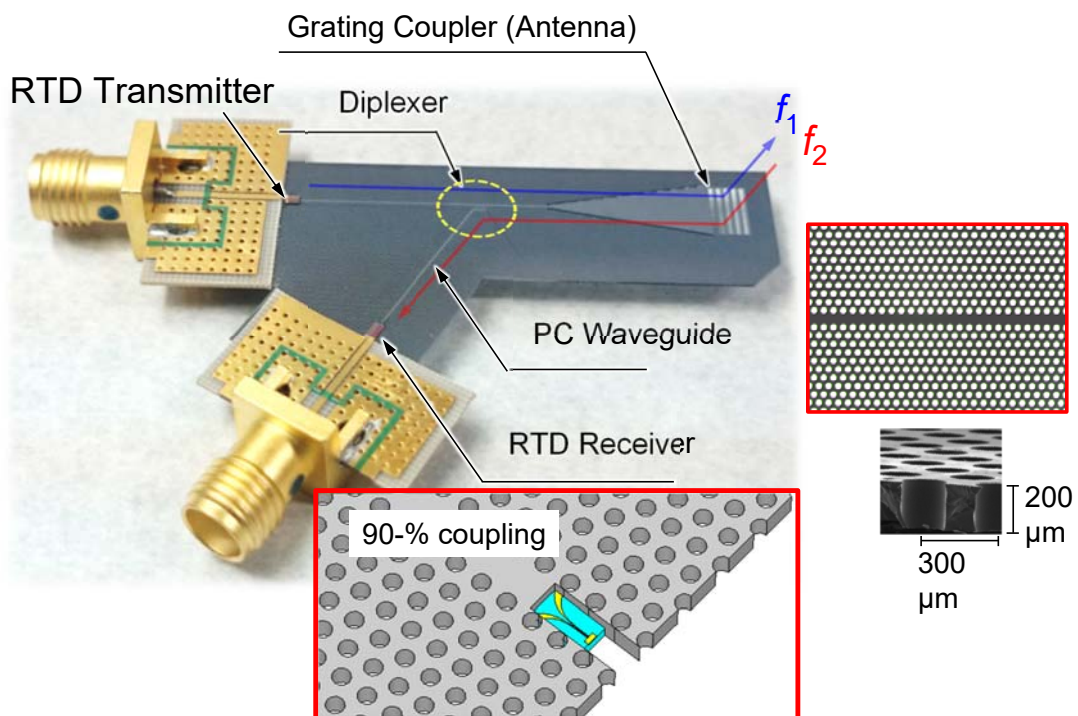


X. Yu., PhD Thesis, Osaka University, 2020.

Dielectric Waveguide Families at Osaka U.



Example of THz System using PhC Waveguide

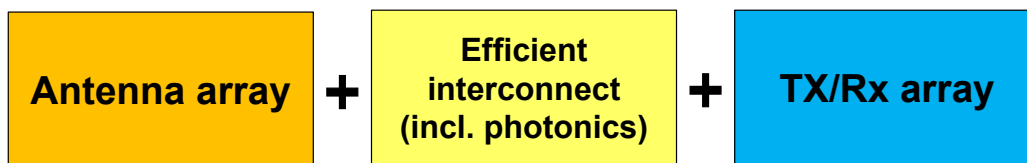


Phased Array Problem in THz Integrated Circuits

2D phased array has not been realized at 300 GHz.

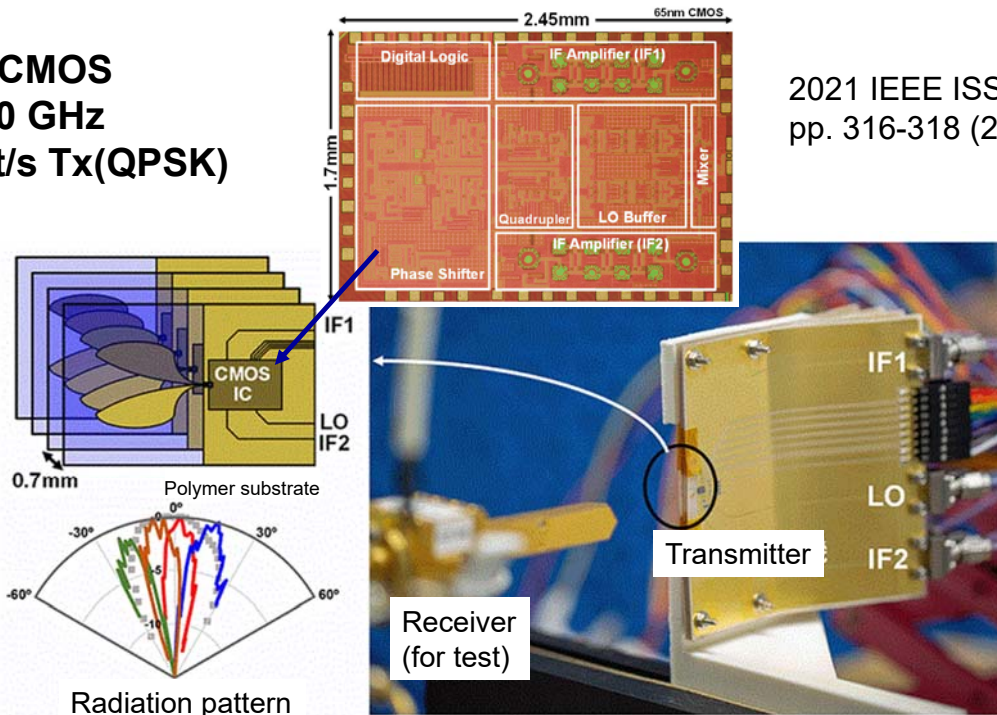
	Antenna pitch ($\lambda/2$)		Chip size
28 GHz (5G)	5~6 mm	>	1 mm
300 GHz (6G)	0.5 mm	<	1 mm

Hybrid integration/packaging



300-GHz-band Si-CMOS Phased Array (Titech)

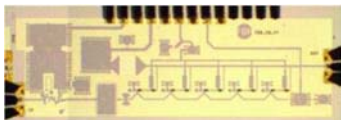
65 nm CMOS
242-280 GHz
52 Gbit/s Tx(QPSK)



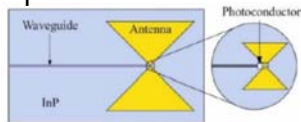
2021 IEEE ISSCC, 22.2, pp. 316-318 (2021)

Expectations for TERAway

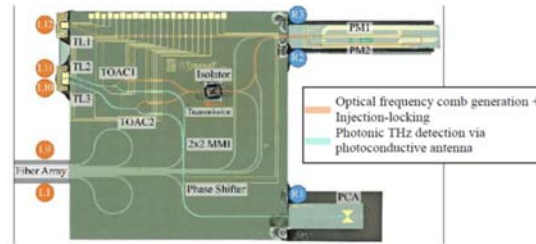
TERAWAY provides key technologies, which all meet future directions!!
~Aggressive integration of electronics and photonics~



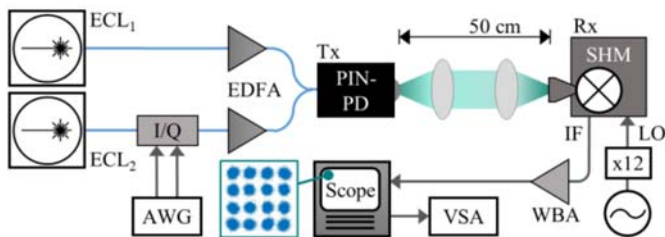
Broadband amplifiers



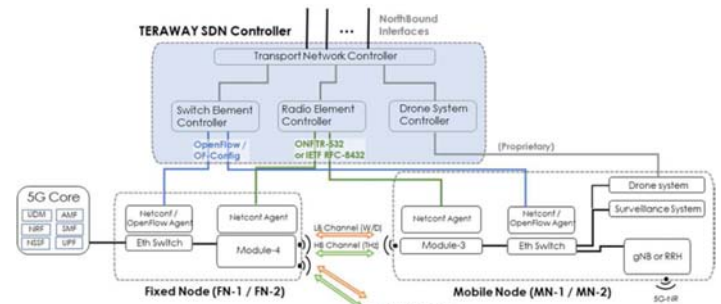
Efficient O/E converters



Integrated photonics-based Rx



THz link using photonics-based Tx



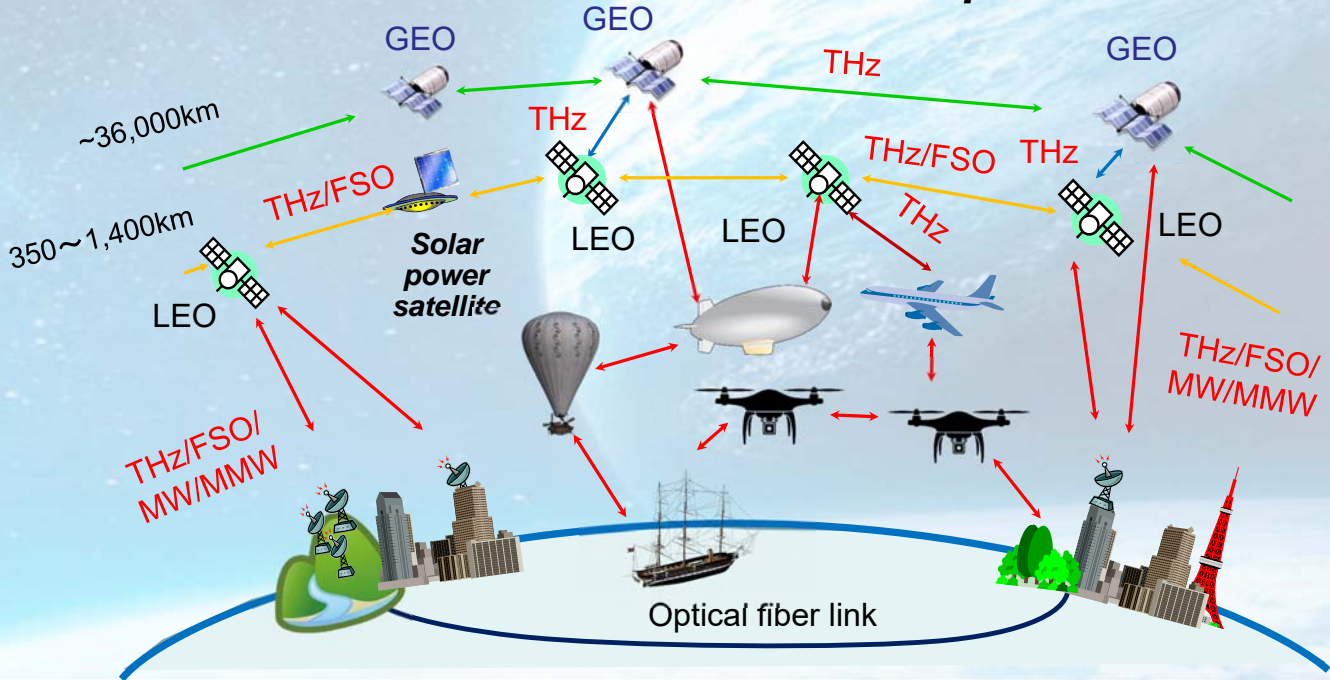
Network architectures

THz x Drone: Students Initiative



6G & Beyond

From 2D NW to Vertical and Space



Thank you for your kind attention.

Acknowledgment

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